

Third-Party Search Results

Citations from Dissertation Abstracts: DIS

1. NDN 135-0097-1501-6: MULTILEVEL INTERCONNECTION TECHNOLOGIES--A FRAMEWORK AND EXAMPLES

Citations from Energy Database: EDB

2. NDN 108-0539-1134-4: Electrophysical investigation of thin-layered inorganic coatings

Citations from Energy Database: ED1

3. NDN 168-0400-4358-5: Microelectronic thin film deposition by ultraviolet laser photolysis

MONOGRAPH TITLE- Laser processing of semiconductor devices

Citations from European Fulltext Granted Patents: EFB

4. NDN 080-0136-2848-4: Method of producing a CMOS inverter on a soi-substrate with a SIMOX technique PATENT NUMBER- 0554063/EP-B1

5. NDN 080-0135-8224-4: Method of enhancing the withstand voltage of a multilayered semiconductor device PATENT NUMBER- 0419898/EP-B1

6. NDN 080-0089-3105-9: PROCESS FOR MANIPULATING MICROSCOPICALLY SMALL DIELECTRIC PARTICLES AND DEVICE FOR IMPLEMENTING THE PROCESS PATENT NUMBER- 0555252/EP-B1

7. NDN 080-0087-3408-1: SEMICONDUCTOR FILM BOLOMETER THERMAL INFRARED DETECTOR PATENT NUMBER- 0526551/EP-B1

8. NDN 080-0086-8425-2: Process for cleaning oxidized metallic surfaces in the fabrication of interconnection networks and boards for such networks PATENT NUMBER- 0518774/EP-B1

9. NDN 080-0085-8741-4: Heat treatment of Si single crystal PATENT NUMBER- 0503816/EP-B1

10. NDN 080-0084-8883-7: Method for testing electrical properties of silicon single crystal PATENT NUMBER- 0487302/EP-B1

11. NDN 080-0064-9017-3: Low temperature plasma nitridation process and applications of nitride films formed thereby PATENT NUMBER- 0201380/EP-B1

12. NDN 080-0061-2955-7: In situ monitoring technique and apparatus for chemical/mechanical planarization endpoint detection PATENT NUMBER- 0455455/EP-B1

13. NDN 080-0020-9005-0: A programmable element for a semiconductor integrated circuit chip PATENT NUMBER- 0224418/EP-B1

Citations from Engineering Index: EI1

14. NDN 017-0162-4540-3: Surface micromachined pressure transducers.

Citations from Engineering Index: EI2

15. NDN 163-0241-9685-5: Measurement of polyimide interlayer adhesion using microfabricated structures.

Citations from INSPEC: IN2

16. NDN 083-0456-5984-0: Residual stress in PZT thin films and its effect on ferroelectric properties

17. NDN 083-0401-5570-3: Stress and stress relaxation in integrated circuit metals and dielectrics

18. NDN 083-0400-0730-0: Properties of a photoimageable thin polyimide film

19. NDN 083-0374-3142-2: Control of thin film materials properties used in high density multichip interconnect

Citations from INSPEC (80-89): IN3

20. NDN 161-0331-2580-8: Metalized MIC substrates using high K dielectric resonator materials

21. NDN 161-0327-9154-3: Stresses in borophosphosilicate glass films during thermal cycling

22. NDN 161-0327-9151-9: Low stress films of cyclized polybutadiene dielectrics by vacuum annealing

23. NDN 161-0325-2065-2: Passivation of GaAs FET's with PECVD silicon nitride films of different stress states

24. NDN 161-0321-3789-5: Characterization of a spin-applied dielectric for use in multilevel metallization

25. NDN 161-0311-1185-9: Material characteristics of spin-on glasses for interlayer dielectric applications

26. NDN 161-0275-3176-3: Stress measurements on multilevel thin film dielectric layers used in Si integrated circuits

27. NDN 161-0212-7483-2: Laser photolytic deposition of thin films

28. NDN 161-0201-7251-6: Low temperature double-exposed polyimide/oxide dielectric for VLSI multilevel metal interconnection

Citations from INSPEC (69-79): IN4

29. NDN 082-0050-6162-5: A switching plate with aluminium membrane crossings of conductors

30. NDN 082-0050-5840-7: Internal stresses and resistivity of low-voltage sputtered tungsten films (microelectronic cct. conductor)

31. NDN 082-0039-2832-0: An evaluation of methods for passivating silicon integrated circuits

Citations from WORLD PATENT FULLTEXT: PC2

32. NDN 052-0140-0809-9: MULTICHP INTEGRATED CIRCUIT MODULE AND METHOD OF FABRICATION, -1992017901/WO-A1/ PUBLICATION NUMBER- 1992017901/WO-A1

33. NDN 052-0124-5626-6: EXTENDED INTEGRATION SEMICONDUCTOR STRUCTURE AND METHOD OF MAKING THE SAME, -1990009093/WO-A1/ PUBLICATION NUMBER- 1990009093/WO-A1

34. NDN 052-0120-6199-1: REDUCING STEREOLITHOGRAPHIC PART DISTORTION THROUGH ISOLATION OF STRESS, -1989010255/WO-A1/ PUBLICATION NUMBER- 1989010255/WO-A1

Citations from US PATENT FULLTEXT: US2

35. NDN 064-2592-7787-5: Method of forming patterned polyimide films PATENT NUMBER- 05470693

36. NDN 064-2519-6676-4: Global planarization process PATENT NUMBER- 05284804

37. NDN 064-2446-9512-4: Avoiding spin-on-glass cracking in high aspect ratio cavities PATENT NUMBER- 05119164

38. NDN 064-2405-8655-8: Method for coplanar integration of semiconductor ic devices PATENT NUMBER- 04990462

39. NDN 064-2381-4169-7: Electro-optic signal measurement PATENT NUMBER- 04928058

Citations from US PATENT FULLTEXT: US3

40. NDN 067-2264-7934-2: Formation and planarization of silicon-on-insulator structures PATENT NUMBER- 04604162

Citations from US PATENT FULLTEXT: US5

41. NDN 196-2443-9436-3: Incorporation of dielectric layers in a semiconductor

Citations from Dissertation Abstracts: DIS

1. MULTILEVEL INTERCONNECTION TECHNOLOGIES--A FRAMEWORK AND

EXAMPLES

DIS 93-18-BK AAI8814014 NDN- 135-0097-1501-6

AUTHORS- PAI, PEI-LIN

Chairman: WILLIAM G. OLDHAM

VOLUME 49-05B

PUBLICATION DATE- 1987

PP 1871

146 PAGES

CORPORATE AUTHOR- UNIVERSITY OF CALIFORNIA, BERKELEY

INSTITUTION CODE- 0028

Degree- PH.D.

SUBFILE CODE- DAI

Document Order Number- AAI8814014

Section- The Sciences and Engineering

LANGUAGE- English (DEF)

Multilevel interconnection is widely practiced today; however, the difficulties in the metal patterning and topography planarization processes motivate more research in interconnection technology. An additive thin-film patterning process (LOPED) is examined, and a planarization process using spin-on glass is investigated. The metallization process in general is studied, and those approaches that can be extended beyond VLSI are selected for more detailed study. I. Thin-film patterning. A new lift-off process using edge-detection (LOPED) can pattern thin films deposited with good step coverage. Some guidelines, including a process window, have been developed for the LOPED process to assure successful patterning. The potential of this process is demonstrated for both metallization and trench isolation. In the lifting step of the LOPED process, acetone penetrates into the patterning resist with a constant speed, leaving a swollen region behind a sharp boundary. The penetration velocity is related to the metal deposition time and volume increase. II.

Planarization. Both the current planarization processes using spin-on glass (SOG) are severely challenged when the underlying metal pitch approaches 2.5\mum unless a sandwich structure (SOG/LTO/SOG) is used. The material properties needed for successful applications of SOG are investigated. Infrared spectrophotometry shows that the concentration of hydroxyl and organic groups are sensitive to the annealing conditions. The stress levels of SOG films on Si wafers are always low (less than 10\sp8Pa in tensile). A strong correlation between the dielectric properties and the OH content in the film is established. SOG IC1-200 (Futurrex Company) shows low dielectric constants and high breakdown fields after 400\sp\circC annealing. III.

Metallization framework. A general examination of the metallization process shows that, under some practical assumptions, there are thirteen ways to construct a metallization process. Out of the thirteen ways, six do not require planarization after interconnect patterning and are considered promising for VLSI and beyond. Selective metal deposition, e.g. electroless plating, is required by all six approaches.

Electroless-plated Ni and Pd may be used for via filling and Cu for interconnects. A buried metal process, either using lift-off or electroless plating, can provide a planarized surface after metallization.

DESCRIPTOR- ENGINEERING, ELECTRONICS AND ELECTRICAL
SECTIONAL CLASSIFICATION CODE- 0544

Citations from Energy Database: EDB

2. Electrophysical investigation of thin-layered inorganic coatings
EDB 91-06 91:034254 91000413221 NDN- 108-0539-1134-4

AUTHORS- Kochugova, I. V.; Nikolaeva, L. V.; Vakser, N. M., (M.I. Kalinin Leningrad Polytechnic Institute (USSR))

JOURNAL NAME- Inorganic Materials (English Translation) (USA)

ABBREVIATED JOURNAL TITLE- Inorg. Mater. (Engl. Transl.)

VOLUME 25

NUMBER 6

PUBLICATION DATE- 1989-11

PP 826-828

DOCUMENT TYPE- Journal Article

ISSN- 0020-1685

CODEN- INOMA

AUTHOR AFFILIATION- M.I. Kalinin Leningrad Polytechnic Institute (USSR)

LOCATION OF WORK- SU

LITERARY INDICATOR- Translation

TRANSLATION INFORMATION- Translation of Izvestiya Akademii Nauk SSSR, Neorganicheskie Materialy; 25: No. 6, 981-983(Jun 1989)

SUBFILE CODE- JMT

PUBLICATION COUNTRY- US

ANNOUNCEMENT CODE- EDB; ETD

INCOMING TAPE SERIAL NUMBER- JT9059%%545

ANNOUNCEMENT IDENTIFICATION- EDB-91:034254

LANGUAGE- English

The electrical resistivity of compositions can be raised by creation of coatings based on glassy binder and highly dispersed fillers. To this end, gelatinous solutions containing 40-65% of tetraethylorthosilicate (TEOS) as the glass-forming component and aqueous salt solutions as well as solutions containing orthophosphoric acid instead of TEOS as the glass-forming component are used. In this work, inorganic coatings (IC) which are prepared from suspensions consisting of powdered filler (50-60 mass %) distributed in a dispersing medium, a solution which forms a glassy-matrix coating upon firing, are studied. Inorganic coatings placed on a metal base as a thin layer (20-25 μ m) combine good electrical insulating properties with pliability and elasticity. The dielectric losses in the compositions studied are defined by conductivity and polarization. They grow with heating. The properties of the coatings, prepared from a suspension of filler in a glass-forming solution, depend mainly on the nature of filler and can change substantially with exchange of one filler by another.

DESCRIPTOR- *ALUMINIUM OXIDES --Electrical properties; *CHROMIUM OXIDES --Electrical properties; *COATINGS --Electrical properties; *ELECTRICAL INSULATION --Electrical properties ACETATES; ALUMINIUM; BINDERS; CAPACITANCE; DIELECTRIC PROPERTIES; DISPERSIONS; ELASTICITY; ELECTRIC CONDUCTIVITY; ELECTRIC CONDUCTORS; FILLERS; GLASS; LOSSES; MATRIX MATERIALS; NICHROME; NICKEL; NITRATES; STAINLESS STEELS; SUBSTRATES; TEMPERATURE DEPENDENCE; THIN FILMS IDENTIFIER- ALLOY-NI60FE24CR16; ALLOYS; ALUMINIUM COMPOUNDS; CARBOXYLIC ACID SALTS; CHALCOGENIDES; CHROMEL; CHROMIUM ALLOYS; CHROMIUM COMPOUNDS; CORROSION RESISTANT ALLOYS; ELECTRICAL PROPERTIES; ELEMENTS; FILMS; HEAT RESISTANT MATERIALS; HEAT RESISTING ALLOYS; HIGH ALLOY STEELS; IRON ALLOYS; IRON BASE ALLOYS; MATERIALS; MECHANICAL PROPERTIES; METALS; NICKEL ALLOYS; NICKEL BASE ALLOYS; NITROGEN COMPOUNDS; OXIDES; OXYGEN COMPOUNDS; PHYSICAL

PROPERTIES; STEELS; TENSILE PROPERTIES; TRANSITION ELEMENT COMPOUNDS;
TRANSITION ELEMENTS
SECTIONAL CLASSIFICATION CODE- 360204

Citations from Energy Database: ED1

3. Microelectronic thin film deposition by ultraviolet laser photolysis
MONOGRAPH TITLE- Laser processing of semiconductor devices
EDB 85-01 85:004392 8411524969 NDN- 168-0400-4358-5

AUTHORS- Boyer, P. K.; Collins, G. J.; Moore, C. A.; Ritchie, W. K.; Roche, G. A.;
Solanski, R.(A); Tang, C. C.(M)

PUBLICATION DATE- 1983

120-126 PAGES

DOCUMENT TYPE- Book Analytic

AUTHOR AFFILIATION- Colorado State Univ., Fort Collins, CO

LOCATION OF WORK- US

LITERARY INDICATOR- Conference

REPORT NUMBER- CONF-830123--

PUBLISHER- SPIE

PUBLICATION PLACE- Bellingham, WA, USA

PUBLICATION COUNTRY- US

CONFERENCE DATE- 24 Jan 1983

CONFERENCE TITLE- International Society for Optical Engineering (SPIE) conference

CONFERENCE LOCATION- Los Angeles, CA, USA

ANNOUNCEMENT CODE- INS; EDB

ANNOUNCEMENT IDENTIFICATION- EDB-85:004392

ORIGINAL SERIAL TITLE- Proceedings of the SPIE, vol. 385

An excimer laser is used to photochemically deposit thin films of silicon dioxide, silicon nitride, aluminum oxide, and zinc oxide at low temperatures (100-350 $^{\circ}$ C). Deposition rates in excess of 3000 Å/min and conformal coverage over vertical walled steps were demonstrated. The films exhibit low defect density and high breakdown voltage and have been characterized using IR spectrophotometry, AES, and C-V analysis. Device compatibility has been studied by using photodeposited films as interlayer dielectrics, diffusion masks, and passivation layers in production CMOS devices. Additionally, the authors deposited metallic films of Al, Mo, W, and Cr over large (>5 cm 2) areas using UV photodissociation of trimethylaluminum and the refractory metal hexacarbonyls. Both shiny metallic films as well as black particulate films were obtained depending on the deposition geometry. The black films are shown to grow in columnar grains. The depositions were made at room temperature over pyrex and quartz plates as well as silicon wafers. They examined the resistivity, adhesion, stress and step coverage of these films. The films exhibited resistivities at most about 20 times that of the bulk materials and tensile stress no higher than 7×10^9 dynes/cm 2 .

DESCRIPTOR- *ALUMINIUM OXIDES --Deposition; *ALUMINIUM OXIDES --Photolysis; *SILICON NITRIDES --Deposition; *SILICON NITRIDES --Photolysis; *SILICON OXIDES --Deposition; *SILICON OXIDES --Photolysis; *ZINC OXIDES --Deposition; *ZINC OXIDES --Photolysis ACOUSTIC ESR; ADHESION;

BREAKDOWN; DEFECTS; DIELECTRIC MATERIALS; DIFFUSION; ELECTRIC CONDUCTIVITY; ELECTRIC POTENTIAL; EXCIMER LASERS; GEOMETRY; GRAIN GROWTH; INFRARED SPECTRA; METALS; MICROELECTRONICS; PARTICULATES; PASSIVATION; PHOTOCHEMISTRY; PYREX; QUARTZ; SPECTROPHOTOMETRY; STRESSES; THIN FILMS IDENTIFIER- ALUMINIUM COMPOUNDS; BOROSILICATE GLASS; CHALCOGENIDES; CHEMICAL REACTIONS; CHEMISTRY; DECOMPOSITION; ELECTRICAL PROPERTIES; ELECTRON SPIN RESONANCE; ELEMENTS; FILMS; GAS LASERS; GLASS; LASERS; MAGNETIC RESONANCE; MATERIALS; MATHEMATICS; MINERALS; NITRIDES; NITROGEN COMPOUNDS; OXIDE MINERALS; OXIDES; OXYGEN COMPOUNDS; PARTICLES; PHOTOCHEMICAL REACTIONS; PHYSICAL PROPERTIES; PNICTIDES; RESONANCE; SILICON COMPOUNDS; SILICON OXIDES; SPECTRA; ZINC COMPOUNDS
SECTIONAL CLASSIFICATION CODE- 360201

Citations from European Fulltext Granted Patents: EFB

4. Method of producing a CMOS inverter on a soi-substrate with a SIMOX technique

EPB 2000-06-28 0554063/EP-B1 NDN- 080-0136-2848-4

INVENTOR- Inoue, Shunsuke, c/o Canon Kabushiki Kaisha 3-30-2, Shimomaruko, Ohta-ku Tokyo JP

INVENTOR- Koizumi, Toru, c/o Canon Kabushiki Kaisha 3-30-2, Shimomaruko, Ohta-ku Tokyo JP

INVENTOR- Miyawaki, Mamoru, c/o Canon Kabushiki Kaisha 3-30-2, Shimomaruko, Ohta-ku Tokyo JP

INVENTOR- Sugawa, Shigetoshi, c/o Canon Kabushiki Kaisha 3-30-2, Shimomaruko, Ohta-ku Tokyo JP

08902095/WO, A; 04409724/US, A; 63142851/JP

PATENT ASSIGNEE- CANON KABUSHIKI KAISHA 30-2, 3-chome, Shimomaruko, Ohta-ku Tokyo JP DESIGNATED COUNTRIES- DE, FR, GB

PATENT NUMBER- 00554063/EP-B1

PATENT APPLICATION NUMBER- 93300572.0

DATE FILED- 1993-01-27

PUBLICATION DATE- 2000-06-28

PATENT PRIORITY INFORMATION- 4049692, 1992-01-31, JP

FIRM- Beresford, Keith Denis Lewis et al, BERESFORD & Co. High Holborn 2-5 Warwick Court, London WC1R 5DJ, GB

INTERNATIONAL PATENT CLASS- H01L02712

PUBLICATION- 1993-08-04; 2000-06-28, B1, Granted patent

SECONDARY TYPE CITATION-

FILING LANGUAGE- ENG

PROCEDURE LANGUAGE- ENG

DESIGNATED COUNTRY- DE, FR, GB

LANGUAGE- ENG

A semiconductor device has an NMOS transistor and a PMOS transistor formed on at least one monocrystal Si region formed in a thin- film Si layer formed on an insulation layer. The thickness TBOXof the insulation layer on which the NMOS and PMOS transistors are formed, the voltage VSSof a low- voltage power supply and the

voltage VDD of a high- voltage power supply for the NMOS and PMOS transistors satisfy a relationship expressed by the following equation: $T_{BOX} > (VDD - V_{SS})^2 / (K_{sub1} \epsilon_{BOX} (Q_{BN} + Q_{BP}))$, where K_{sub1} (identical with) $2(\phi_{FN})^2$, ϵ_{BOX} is the dielectric constant of the base insulation layer, Q_{BN} and Q_{BP} are bulk charges when the widths of depletion layers of the NMOS and PMOS transistors are maximized, and $(\phi_{FN})^2$ and $(\phi_{FP})^2$ are pseudo Fermi potentials of the NMOS and PMOS transistors.

EXEMPLARY CLAIMS- A method of producing a thin-film CMOS inverter circuit comprising: a monocrystalline silicon bulk semiconductor substrate (1); an insulation layer (2) on said semiconductor substrate; a thin-film Si layer (4 to 7,10,11,12,12',13,13') on said insulation layer; a thin-film NMOS transistor (16) having a source (4,12) and a drain (5,15) in a first isolated monocrystal region (4,5,10,12,12') of said thin-film Si layer, a source electrode (14), a drain electrode (15), and an insulated gate electrode (9); a thin-film PMOS transistor (17) having a source (7,13') and a drain (6,13) in a second isolated monocrystal region (6,7,11,13,13') of said thin-film Si layer, a source electrode (14'), a drain electrode (15') and an insulated gate electrode (9'); a common input electrode connected to said gate electrode of said NMOS transistor and to said gate electrode of said PMOS transistor; a common output electrode connected to said drain electrode of said NMOS transistor and to said drain electrode of said PMOS transistor; a low-voltage power supply, connected to said source electrode of said NMOS transistor, to supply a first voltage, V_1 volts, thereto; and; a high-voltage power supply connected to said source electrode of said PMOS transistor to supply a second voltage, V_2 volts, thereto; wherein; the thickness T_{BOX} of said insulation (2) satisfies a relationship expressed by the following expression: $T_{BOX} > (V_2 - V_1)^2 / (2K_{sub2} \epsilon_{BOX} (Q_{BN} + Q_{BP}))$, where; K_{sub2} (identical with) $2(\phi_{FN})^2$; ϵ_{BOX} is a dielectric constant of said base insulation layer (2), Q_{BN} and Q_{BP} are bulk charges when the widths of depletion layers of said NMOS and PMOS transistors (16,17) are maximized and are expressed in units of Coulombs/cm²; and $(\phi_{FN})^2$ and $(\phi_{FP})^2$ are pseudo Fermi potentials of the NMOS and PMOS transistors.

5. Method of enhancing the withstand voltage of a multilayered semiconductor device

EPB 2000-05-31 0419898/EP-B1 NDN- 080-0135-8224-4

INVENTOR- Schulze, Hans-Joachim, Dr. Ottostrasse 60 f D-8012 Ottobrunn
DE

INVENTOR- Mitlehner, Heinz, Dr. Hohenzollernstrasse 104 D-8000 Munchen 40
DE

02738152/DE-A; 04043837/US-A; 04177477/US-A; 04792530/US-A

PATENT ASSIGNEE- SIEMENS AKTIENGESELLSCHAFT Wittelsbacherplatz 2 80333
Munchen DE DESIGNATED COUNTRIES- CH, DE, FR, GB, LI, SE

PATENT NUMBER- 00419898/EP-B1

PATENT APPLICATION NUMBER- 90117012.6

DATE FILED- 1990-09-04

PUBLICATION DATE- 2000-05-31

PATENT PRIORITY INFORMATION- 3932489, 1989-09-28, DE

INTERNATIONAL PATENT CLASS- H01L021332; H01L021331; H01L021263;
H01L021225; H01L021266; H01L02932; H01L029167; H01L02974

PUBLICATION- 1991-04-03; 1994-07-20; 2000-05-31, B1, Granted patent

SECONDARY TYPE CITATION-

FILING LANGUAGE- GER

PROCEDURE LANGUAGE- GER

DESIGNATED COUNTRY- CH, DE, FR, GB, LI, SE

LANGUAGE- GER

EXEMPLARY CLAIMS- Method of increasing the dielectric strength of a semiconductor component in wafer form, with four successive layers: an emitter layer (1) of a first conductivity type, a base layer (2) of a second conductivity type, a base layer (3) of the first conductivity type and a second emitter layer (4) of the second conductivity type, in which the emitter layer of the first conductivity type has a connection to a cathode (K) and the emitter layer of the second conductivity type has a connection to the anode (A), and in which there is a first pn junction (7) between the base layer of the first conductivity type and the base layer of the second conductivity type and a second pn junction (8) between the base layer of the first conductivity type and the emitter layer of the second conductivity type, characterized in that a central active region (LBz) of the semiconductor component is covered with an exposure mask in such a way that proton exposure of the semiconductor component takes place only in a region (LBr) of positively bevelled edge connections (12, 13) which are provided in order to reduce the surface field strength, in that a relatively thin zone (16, 17) in comparison with the thickness of the base layer of the first conductivity type is created in the lateral region (LBr) outside the exposure mask and vertically between the first and second pn junctions, the thin zone (16) having a reduced charge-carrier lifetime compared with the base layer of the first conductivity type and the exposure energy of the proton radiation being designed such that the thin zone with the reduced charge-carrier lifetime lies outside the space-charge zone created as a result of the reverse blocking voltage at the first and/or second pn junction (7, 8).

NO-DESCRIPTORS .

6. PROCESS FOR MANIPULATING MICROSCOPICALLY SMALL DIELECTRIC PARTICLES AND DEVICE FOR IMPLEMENTING THE PROCESS

EPB 1996-02-07 0555252/EP-B1 NDN- 080-0089-3105-9

INVENTOR- BENECKE, Wolfgang Sigismundstr. 5 D-1000 Berlin 30 DE

INVENTOR- WAGNER, Bernd Potsdamer Ch. 31c D-1000 Berlin 38 DE

INVENTOR- FUHR, Gunter Str. 64, Nr. 6, 13-19 D-1113 Berlin DE

INVENTOR- HAGEDORN, Rolf Wartinerstr. 16 D-1094 Berlin DE

INVENTOR- MULLER, Thorsten Hartriegelstr. 100 D-1190 Berlin DE

PATENT ASSIGNEE- FRAUNHOFER-GESELLSCHAFT ZUR FORDERUNG DER

ANGEWANDTEN FORSCHUNG E. V. Leonrodstrasse 54 80636 Munchen DE

DESIGNATED COUNTRIES- CH, DE, FR, GB, IT, LI, NL

PATENT NUMBER- 00555252/EP-B1

PATENT APPLICATION NUMBER- 91918107.3

DATE FILED- 1991-10-28; 1991-10-28

PUBLICATION DATE- 1996-02-07

PATENT PRIORITY INFORMATION- 4034697, 1990-10-31, DE

FIRM- Munich, Wilhelm, Dr. et al, Kanzlei Munich, Steinmann, Schiller Wilhelm-Mayr-Str. 11, 80689 Munchen, DE

INTERNATIONAL PATENT CLASS- B03C00500; B03C00502; G01N01500

PCT PUBLICATION DATE- 1992-05-14

PUBLICATION- 1993-08-18; 1993-08-18; 1996-02-07, B1, Granted patent

SECONDARY TYPE CITATION-

FILING LANGUAGE- GER

PROCEDURE LANGUAGE- GER

DESIGNATED COUNTRY- CH, DE, FR, GB, IT, LI, NL

LANGUAGE- GER

EXEMPLARY CLAIMS- Device for manipulating microscopic dielectric particles, comprising:; a substrate body,; a multi- electrode system disposed on said substrate body for generating a travelling electric field, and including electrodes disposed adjacent to each other approximately orthogonally to the travelling direction of said travelling field, and; an electronic circuit for successive application of appropriate electrical voltages to said electrodes,; in that both the spacing and the widths of said electrodes are smaller than the diameter of the particles to be manipulated, and that the travelling frequencies of said electric fields range from 0.1 to 100 MHz.; Device according to Claim 1,; in that said electrodes present an elongate rectangular shape and are equidistantly disposed in parallel to each other such that the direction of said travelling field extends orthogonally to the longitudinal axes of said electrodes.; Device according to Claim 1 or 2,; in that, starting out from an electrode in the central region of said multi-electrode system, said electrodes present discontinuities in a region diverging in V-shape in the direction of said travelling field, wherein said electrodes are bent off in the vicinity of said discontinuity in such a way that they open at right angles into said V- shaped region.; Device according to any of Claims 1 to 3,

NO-DESCRIPTORS .

7. SEMICONDUCTOR FILM BOLOMETER THERMAL INFRARED DETECTOR

EPB 1996-12-11 0526551/EP-B1 NDN- 080-0087-3408-1

INVENTOR- LIDDIARD, Kevin, Charles 18 Ferrier Avenue Fairview Park, S.A. 5126 AU

PATENT ASSIGNEE- THE COMMONWEALTH OF AUSTRALIA c/o the Secretary Department of Defence Support, Anzac Park West Building, Constitution Avenue Canberra, Australian Capital Territory 2600 AU DESIGNATED COUNTRIES- BE, CH, DE, FR, GB, IT, LI, NL, SE

PATENT NUMBER- 00526551/EP-B1

PATENT APPLICATION NUMBER- 91908757.7

DATE FILED- 1991-04-24; 1991-04-24

PUBLICATION DATE- 1996-12-11

PATENT PRIORITY INFORMATION- 981390, 1990-04-26, AU

FIRM- Opperman, Stuart Richard et al, Haseltine Lake & Co. Hazlitt House 28 Southampton Buildings Chancery Lane, London WC2A 1AT, GB

INTERNATIONAL PATENT CLASS- G01J00520

PCT PUBLICATION DATE- 1991-10-31

PUBLICATION- 1993-02-10; 1996-12-11, B1, Granted patent

SECONDARY TYPE CITATION-

FILING LANGUAGE- ENG

PROCEDURE LANGUAGE- ENG

DESIGNATED COUNTRY- BE, CH, DE, FR, GB, IT, LI, NL, SE

LANGUAGE- ENG

EXEMPLARY CLAIMS- An infrared detector comprising a supporting substrate (6) with a cavity formed therein, a dielectric pellicle (5) of low thermal conductivity material suspended over the cavity in the substrate (6) and a heat-sensitive layer (1) with thin metallic contacts (9) thereto deposited on the pellicle (5), characterised in that the dielectric pellicle (5) includes holes or slots (8) through which the cavity is

formed by etching and the heat-sensitive layer (1) with thin metallic contacts (9) is an optical interference filter in which a heat-sensitive semiconductor layer (3) is sandwiched between first and second thin film metallic contacts formed as layers (2, 4), the thickness of the heat-sensitive semiconductor layer (3) being substantially equal to one quarter of the wavelength ((lambda)) of the infrared wavelength to be detected, multiplied by its refractive index (n).; An infrared detector according to claim 1, characterised in that the supporting substrate (6) is a monocrystalline silicon wafer and the cavity is formed by anisotropic etching using a chemical etchant selected from hydrazine, ethylene diamine pyrocatechol or potassium hydroxide.; An infrared detector according to claim 1 or 2, characterised in that the first conductor layer (2) has a resistance of less than 10 ohms per square and the second conductor layer (4) has a resistance of between 300 and 500 ohms per square, the second layer (4) being disposed above the first layer (2) in order to receive the first infrared radiation to be detected.; An infrared detector according to claim 1, 2 or 3, characterised in that the heat-sensitive semiconductor layer (3) is a layer of silicon prepared by sputter or chemical vapour deposition.; An infrared detector according to any one of the preceding claims, characterised in that the thin film metallic layers (2, 4) are formed from one or more layers of nickel, nickel-chromium, platinum, platinum silicide or tantalum silicide.

NO-DESCRIPTORS .

8. Process for cleaning oxidized metallic surfaces in the fabrication of interconnection networks and boards for such networks

EPB 1996-03-06 0518774/EP-B1 NDN- 080-0086-8425-2

INVENTOR- Templier, Francois 36, avenue Felix Viallet F-38000 Grenoble FR
INVENTOR- Torres, Joaquim 236 Chemin Francy F-38950 Saint- Martin-le-

Vinoux FR

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00129490/EP-A; 00300414/EP-A; 00387097/EP-A; 04706870/US-A

PATENT ASSIGNEE- FRANCE TELECOM 6, Place d'Alleray 75015 Paris FR

DESIGNATED COUNTRIES- DE, GB

PATENT NUMBER- 00518774/EP-B1

PATENT APPLICATION NUMBER- 92401628.0

DATE FILED- 1992-06-12

PUBLICATION DATE- 1996-03-06

PATENT PRIORITY INFORMATION- 9107325, 1991-06-14, FR

FIRM- Casalonga, Axel et al, BUREAU D.A. CASALONGA - JOSSE Morassistrasse 8, 80469 Munchen, DE

INTERNATIONAL PATENT CLASS- C23G00500; C23C01650; H01L021768; H01L021321

PUBLICATION- 1992-12-16; 1992-12-16; 1996-03-06, B1, Granted patent

SECONDARY TYPE CITATION-

FILING LANGUAGE- FRE

PROCEDURE LANGUAGE- FRE

DESIGNATED COUNTRY- DE, GB

LANGUAGE- FRE

une premiere couche conductrice metallisee, une couche dielectrique deposee sur la couche metallisee, puis gravee pour denuder les surfaces a metalliser ou trous de contact, et une seconde couche metallisee deposee sur la surface gravee, caracterise en ce que les plaquettes gravees sont traitees par plasma multipolaire micro-onde

sous hydrogene avant le depot de la seconde couche metallisee. Elle concerne également les plaquettes pour reseaux d'interconnexions dans lesquels les surfaces metallisees ont ete nettoyees selon l'invention.

EXEMPLARY CLAIMS- A process for cleaning oxidized metallized surfaces, employed in the manufacture of wafers for interconnection networks, comprising at least:; a first metallized conducting layer,; a dielectric layer deposited on the metallized layer and then etched in order to bare the surfaces to be metallized or contact holes, and; a second metallized layer deposited on the etched surface, wherein the etched wafers are treated using microwave multipolar plasma under hydrogen before the deposition of the second metallized layer.; The process as claimed in claim 1, wherein the first metallized conducting layer and/or the second metallized conducting layer essentially consists or consist of copper, nickel or tungsten.; The process as claimed in claim 1 or 2, wherein the first metallized conducting layer and/or the second metallized conducting layer essentially consists or consist of copper.; The process as claimed in one of claims 1 to 3, wherein the treatment using microwave multipolar plasma is carried out at a temperature lying between 0.C and 400.C.; The process as claimed in one of claims 1 to 4, wherein the treatment using microwave multipolar plasma under hydrogen is carried out at ambient temperature.; The process as claimed in one of claims 1 to 5, wherein the treatment using microwave multipolar plasma is assisted by bias of the substrate, the bias voltage varying from 0 to 1000 volts.; The process as claimed in one of claims 1 to 6, wherein the treatment using microwave multipolar plasma under hydrogen is carried out in the same chamber as the deposition.; The process as claimed in one of claims 1 to 7, wherein the treatment using microwave multipolar plasma under hydrogen is directly preceded by an etching treatment using microwave multipolar plasma under oxygen.; Procede de nettoyage de surfaces metallisees oxydees mises en oeuvre dans la fabrication des plaquettes pour reseaux d'interconnexions, comportant au moins :; une premiere couche conductrice metallisee,

NO DESCRIPTORS .

9. Heat treatment of Si single crystal

EPB 1996-09-18 0503816/EP-B1 NDN- 080-0085-8741-4

INVENTOR- Fusegawa, Izumi Yanase 791-4, Annaka-shi Gunma-ken JP
INVENTOR- Yamagishi, Hirotoshi Annaka 1721-3, Annaka-shi Gunma- ken JP
INVENTOR- Fujimaki, Nobuyoshi Yanase 117-201, Annaka-shi Gunma- ken JP

INVENTOR- Karasawa, Yukio Koh 856, Kenzaki-machi Takasaki-shi, Gunma- ken JP

00390672/EP-A; 02080780/GB-A; 02182262/GB-A; 57200293/JP-A

PATENT ASSIGNEE- SHIN-ETSU HANDOTAI COMPANY LIMITED 4-2, Marunouchi 1-Chome Chiyoda-ku Tokyo JP DESIGNATED COUNTRIES- DE, FR, GB

PATENT NUMBER- 00503816/EP-B1

PATENT APPLICATION NUMBER- 92301795.8

DATE FILED- 1992-03-03

PUBLICATION DATE- 1996-09-18

PATENT PRIORITY INFORMATION- 76876/91, 1991-03-15, JP

FIRM- Pacitti, Pierpaolo A.M.E. et al, Murgitroyd and Company 373 Scotland Street, Glasgow G5 8QA, GB

INTERNATIONAL PATENT CLASS- C30B03302; C30B01500; C30B02906

PUBLICATION- 1992-09-16; 1992-09-16; 1996-09-18, B1, Granted patent

SECONDARY TYPE CITATION-
FILING LANGUAGE- ENG
PROCEDURE LANGUAGE- ENG
DESIGNATED COUNTRY- DE, FR, GB
LANGUAGE- ENG

The method of this Invention for heat treatment of a Si single crystal grown by the Czochralski method at a speed of pull of not less than 0.8 mm/min., characterized by heat-treating at a temperature in the range of from 1,150 .C to 1,280 .C a wafer cut out of the SI single crystal thereby producing a Si wafer excellent in oxide film dielectric breakdown voltage characteristic due to elimination of crystal defects. Consequently, this invention ensures production of LSI in a high yield.

EXEMPLARY CLAIMS- A method for heat treatment of a wafer cut out of a Si single crystal bar grown by the Czochralski method at a speed of pull exceeding 0.8 mm/min. and not higher than 1.6 mm/min. at a temperature in the range 1150.C to 1280.C for the purpose of obtaining a Si single crystal wafer with an improved oxide film dielectric breakdown voltage; characterised by:; determining, in advance, a first correlation between the oxide film breakdown voltage and the density of scale-like patterns as obtained by selective etching of the wafer, and a second correlation between said density of scale-like patterns and the time period of the heat treatment; and; heat treating the Si single crystal wafer within said temperature range in an atmosphere of dry oxygen for a time period of at least 10 minutes, selected on the basis of said first and second correlations such that the Si single crystal wafer has a density of scale-like patterns not higher than 200 counts/cm; after the heat treatment, which is required to improve the oxide film dielectric breakdown voltage to not less than 8MV/cm.; The method for heat treatment as claimed in Claim 1, wherein the time period of the heat treatment is selected on the basis of said correlation such that a wafer having a density of scale-like patterns between 500 counts/cm; 2and 3000 counts/cm; 2in advance of the heat treatment has said density of scale-like patterns no higher than 200 counts/cm; after the heat treatment.; Methode de traitement thermique d'une galette decoupee dans un barreau de Si monocristallin obtenu par tirage selon le procede Czochralski a une vitesse de tirage superieure a 0,8 mm/min mais ne depassant pas 1,6 mm/min, a une temperature comprise entre 1150 et 1280.C, afin d'obtenir une galette de Si monocristallin ayant une meilleure tension dielectrique de claquage du film d'oxyde,; caracteriseen ce qu'elle comprend :

NO-DESCRIPTORS .

10. Method for testing electrical properties of silicon single crystal
EPB 1996-06-05 0487302/EP-B1 NDN- 080-0084-8883-7

INVENTOR- Fusegawa, Izumi Yanase 791-4 Annaka-shi, Gunma-ken JP
INVENTOR- Yamagishi, Hirotoshi Annaka 1721-3 Annaka-shi, Gunma- ken JP
INVENTOR- Fujimaki, Nobuyoshi Yanase 117-201 Annaka-shi, Gunman- ken JP
INVENTOR- Karasawa, Yukio Koh 856, Kenzaki-machi Takasaki-shi, Gunma- ken JP
03223664/DE, A; 60146000/JP; 52122479/JP; 63215041/JP; 000220707/XP
PATENT ASSIGNEE- SHIN-ETSU HANDOTAI COMPANY LIMITED 4-2, Marunouchi 1-
Chome Chiyoda-ku Tokyo JP DESIGNATED COUNTRIES- DE, FR, GB
PATENT NUMBER- 00487302/EP-B1
PATENT APPLICATION NUMBER- 91310648.0

DATE FILED- 1991-11-19

PUBLICATION DATE- 1996-06-05

PATENT PRIORITY INFORMATION- 320467/90, 1990-11-22, JP

FIRM- Pacitti, Pierpaolo A.M.E. et al, Murgitroyd and Company 373 Scotland Street, Glasgow G5 8QA, GB

INTERNATIONAL PATENT CLASS- G01N02792; C30B03300; C30B03308

PUBLICATION- 1992-05-27; 1993-11-18; 1996-06-05, B1, Granted patent

SECONDARY TYPE CITATION-

FILING LANGUAGE- ENG

PROCEDURE LANGUAGE- ENG

DESIGNATED COUNTRY- DE, FR, GB

LANGUAGE- ENG

The evaluation of the oxide film dielectric breakdown voltage of a silicon semiconductor single crystal is carried out by cutting a wafer out of the single crystal rod, etching the surface of the wafer with the mixed solution of hydrofluoric acid and nitric acid thereby relieving the wafer of strain, then etching the surface of the wafer with the mixed solution of K₂Cr₂O₇, hydrofluoric acid, and water thereby inducing occurrence of pits and scale-like patterns on the surface, determining the density of the scale-like patterns, and computing the oxide film dielectric breakdown voltage by making use of the correlating between the density of scale-like patterns and the oxide film dielectric breakdown voltage. This fact established the method of this invention to be capable of effecting an evaluation equivalent to the evaluation of the oxide film dielectric breakdown voltage of a PW wafer prepared from the single crystal rod.

EXEMPLARY CLAIMS- A method for testing electrical properties of a silicon single crystal, characterized by pulling up a silicon semiconductor single crystal by the Czochralski method or the floating zone pulling method, cutting a wafer of a prescribed thickness from said single crystal, etching the surface of the wafer with a mixed solution of hydrofluoric acid and nitric acid thereby relieving said wafer of strain, then setting the wafer upright in a mixed solution of K; 2Cr; 2O; , hydrofluoric acid and water and selectively etching the surface of the wafer therein for a period in the range from 10 to 60 minutes, and taking count of the number of scale-like patterns consequently appearing on the surface of the wafer, thereby evaluating the oxide film dielectric breakdown voltage of said silicon single crystal.; Methode pour contrôler les propriétés électriques d'un monocristal de silicium, caractérisée en ce :; on réalise un monocristal de silicium semi-conducteur par la méthode de Czochralski ou la méthode de la zone flottante,; on découpe une galette d'épaisseur déterminée dudit monocristal,; on grave la surface de la galette par application d'une solution d'acide fluorhydrique et d'acide nitrique pour dégager ladite galette des contraintes,; ensuite, on place verticalement la galette dans une solution de K; 2Cr; 2O; , d'acide fluorhydrique et d'eau,; puis on grave sélectivement la surface de la galette au sein de cette solution pendant des périodes de durée comprises entre 10 et 60 minutes,; enfin, on compte le nombre de motifs en forme de dépôt apparaissant à la surface de la galette pour ainsi évaluer la tension dielectrique de claquage du film d'oxyde dudit monocristal de silicium.

NO-DESCRIPTORS .

11. Low temperature plasma nitridation process and applications of nitride films formed thereby

EPB 1995-08-09 0201380/EP-B1 NDN- 080-0064-9017-3

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INVENTOR- Petro, William G. 10369 Leola Court Cupertino California 95014
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INVENTOR- Barry, Michael L. 1221 Dana Avenue Palo Alto California 94301 US

00015694/EP-A

PATENT ASSIGNEE- FAIRCHILD SEMICONDUCTOR CORPORATION 10400
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COUNTRIES- DE, FR, GB, IT, NL

PATENT NUMBER- 00201380/EP-B1

PATENT APPLICATION NUMBER- 86400742.2

DATE FILED- 1986-04-08

PUBLICATION DATE- 1995-08-09

PATENT PRIORITY INFORMATION- 721422, 1985-04-09, US; 801955, 1985-11-26,
US

FIRM- Sparing Rohl Henseler Patentanwalte, Postfach 14 04 43, 40074 Dusseldorf,
DE

INTERNATIONAL PATENT CLASS- H01L021318; H01L02943

PUBLICATION- 1986-12-17; 1988-01-13; 1995-08-09, B1, Granted patent

SECONDARY TYPE CITATION-

FILING LANGUAGE- ENG

PROCEDURE LANGUAGE- ENG

DESIGNATED COUNTRY- DE, FR, GB, IT, NL

LANGUAGE- ENG

A silicon nitride layer is prepared on the surface of a silicon substrate by carrying out a surface reaction on the substrate in a vacuum chamber that contains an electrode which is capacitively coupled to an rf generator. A second electrode within the chamber, or a metal wall of the chamber itself, is connected to ground. The silicon substrates to be treated are placed on one of the electrodes to be in electrical and physical contact therewith, and a reagent gas that contains nitrogen is introduced into the chamber. An rf voltage is then applied between the electrodes to ionize and activate the gas, and cause ions and other active species thereof to be directed into the silicon substrate. The nitrogen ions and other active species that are created as a result of the application of the rf power can be directed at the surface of a number of wafers simultaneously. The thin nitride films that are formed by the process have application both as barriers for device isolation and as dielectric components of electrical devices.

EXEMPLARY CLAIMS- A method of preparing a thin film of silicon nitride or other nitrogen-containing composition on a silicon substrate, comprising the steps of: placing one surface of silicon substrate in contact with a first of a pair of plate electrodes, said first electrode being spaced away and opposite from a second plate electrode of said pair of electrodes which faces the opposite surface of said substrate and has an area greater than said first of said pair of electrodes; evacuating a chamber in which said electrodes and the substrate are located; introducing a nitrogen-containing reagent gas free of silicon compounds into the space between said pair of electrodes; and applying an a.c. voltage having a frequency of about 10 KHz or greater between said electrodes to thereby ionize and activate the reagent gas and accelerate ions thereof into the substrate while cooling said first of said pair of electrodes to inhibit heating of said substrate wherein the temperature of said substrate is less than 200.C.; The method of claim 1 wherein said reagent gas

comprises one of pure nitrogen, ammonia and a nitrogen-hydrogen mixture.; The method of claim 1 further including the step of annealing the thin film of nitride formed on said substrate.; The method of claim 3 wherein said annealing step is carried out in the presence of a non- oxidizing gas.; The method of claim 1 wherein the area of the other electrode of said pair of electrodes is at least twice as great as the area of said one electrode.; The method of one of the preceding claims for isolating active regions from one another in an integrated circuit , comprising the steps of: removing selected portions of said film so that the remaining portions of the film correspond to areas in which active devices are to be formed in the wafer; and oxidizing the areas on said surface of the wafer that are not covered by the remaining portions of the nitride film.

NO-DESCRIPTORS .

12. In situ monitoring technique and apparatus for chemical/mechanical planarization endpoint detection

EPB 1994-09-07 0455455/EP-B1 NDN- 080-0061-2955-7

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INVENTOR- Wagner, Eric Richard 400 Rahway Avenue South Plainfield, New Jersey 07080 US

02895264/US-A; 03063206/US-A; 59129664/JP-A

PATENT ASSIGNEE- AT&T Corp. 32 Avenue of the Americas New York, NY 10013-2412 US DESIGNATED COUNTRIES- DE, DK, ES, FR, GB, IT, NL, SE

PATENT NUMBER- 00455455/EP-B1

PATENT APPLICATION NUMBER- 91303869.1

DATE FILED- 1991-04-29

PUBLICATION DATE- 1994-09-07

PATENT PRIORITY INFORMATION- 517106, 1990-05-01, US

FIRM- Johnston, Kenneth Graham et al, Lucent Technologies (UK) Ltd, 5 Mornington Road, Woodford Green Essex, IG8 OTU, GB

INTERNATIONAL PATENT CLASS- B24B03704; B23Q015007

PUBLICATION- 1991-11-06; 1992-04-15; 1994-09-07, B1, Granted patent

SECONDARY TYPE CITATION-

FILING LANGUAGE- ENG

PROCEDURE LANGUAGE- ENG

DESIGNATED COUNTRY- DE, DK, ES, FR, GB, IT, NL, SE

LANGUAGE- ENG

This invention provides an in situ monitoring technique and apparatus (20) for chemical/mechanical planarization end point detectionin the process of fabricating semiconductor or optical devices. Fabrication of semiconductor or optical devices often requires smooth planar surfaces, either on the surface of a wafer (2) being processed or at some intermediate stage e.g. a surface of an interleaved layer. The detection in the present invention is accomplished by means of capacitively measuring the thickness of a dielectric layer (4) on a conductive substrate. The measurement involves the dielectric layer (4), a flat electrode structure (25) and a liquid (20) interfacing the article and the electrode structure. Polishing slurry acts as the interfacing liquid. The electrode structure includes a measuring electrode (26), an insulator surrounding the measuring electrode (28,29), a guard electrode (27) and another insulator surrounding the guard electrode. In the measurement a drive voltage is supplied to the measuring electrode, and in a bootstrap arrangement to a

surrounding guard electrode, thereby measuring the capacitance of the dielectric layer of interest without interfering effect from shunt leakage resistance. The process and apparatus are useful not only for measuring the thickness of dielectric layers on conductive substrates in situ, during planarizing polishing, but also for measuring the dielectric thickness on substrates in other processes, e.g. measuring the dielectric layer thickness prior to or after an etching process.

EXEMPLARY CLAIMS- A process for in situ monitoring the thickness of a dielectric material (4) on a surface (5) of an electrically conductive substrate (2) having less than about one megohm-cm resistivity, characterised by placing the substrate so that a surface of an electrode structure (25) faces the dielectric material, interposing between the substrate and the surface of the electrode structure a film of a conductive liquid (20) with resistivity of less than about 100,000 ohm-cm, said film being in contact with the dielectric material (4) and the surface of the electrode structure, and measuring the capacitance between the substrate (2) and the electrode structure (25).; The process of claim 1 or 14, wherein said measuring includes measuring the capacitance and simultaneously removing from the result the effects of leakage resistance paths.; The process of claim 1, 2, or 14, wherein the capacitive measurement comprises applying a measuring voltage to a measuring electrode (26) of the electrode structure (25) and a bootstrapping guard voltage to a narrow conductive area surrounding the measuring electrode, said measuring electrode and said narrow conductive area being insulated each from another with or without another insulator surrounding the guard electrode (27).; The process of claim 3 or 14, wherein said measuring comprises maintaining constant displacement current resulting from said voltage application, the amplitude of the drive voltage thereby being proportional to the thickness of the dielectric layer (4).

NO-DESCRIPTORS .

13. A programmable element for a semiconductor integrated circuit chip
EPB 1991-01-23 0224418/EP-B1 NDN- 080-0020-9005-0

INVENTOR- Nawata, Takahiro 3, Azamino 4-chome Midori-ku Yokohama- shi Kanagawa 227 JP

INVENTOR- Wada, Kunihiko Pakusaido Musashikosugi 403 658-1, Miyauchi Nakahara-ku Kawasaki-shi Kanagawa 211 JP

INVENTOR- Sato, Noriaki 28-21, Tsurukawa 4-chome Machida-shi Tokyo 194-01 JP

03576549/US-A; 03793090/US-A; 0000#####; 57103348/JP-A

PATENT ASSIGNEE- FUJITSU LIMITED 1015, Kamikodanaka, Nakahara-ku Kawasaki-shi, Kanagawa 211 JP DESIGNATED COUNTRIES- DE, FR, GB

PATENT NUMBER- 00224418/EP-B1

PATENT APPLICATION NUMBER- 86402644.8

DATE FILED- 1986-11-28

PUBLICATION DATE- 1991-01-23

PATENT PRIORITY INFORMATION- 268539/85, 1985-11-29, JP

FIRM- Descourtieux, Philippe et al, Cabinet Beau de Lomenie 158, rue de l'Universite, 75340 Paris Cedex 07, FR

INTERNATIONAL PATENT CLASS- H01L02710; G11C01700

PUBLICATION- 1987-06-03; 1987-06-03; 1991-01-23, B1, Granted patent

SECONDARY TYPE CITATION-

FILING LANGUAGE- ENG

PROCEDURE LANGUAGE- ENG

DESIGNATED COUNTRY- DE, FR, GB

LANGUAGE- ENG

A programmable element for a semiconductor integrated circuit device is formed from a couple of electrode layers(34,36) and an insulating layer (31) intervening therebetween and is programmed by applying a voltage between the electrode layers to cause an electrical breakdown and form a conduction path in the insulating layer. The insulating layer (31) comprises two films (32,33) of different dielectric materials, such as silicon nitride and silicon-dioxide successively formed on the lower electrode layer. Typically, the Si_{(sub)3}N_{(sub)4} film has a thickness in the range between 5 and 20 nm and the SiO_{(sub)2} film has a thickness in the range between 05 and 10 nm. The composite structure of the insulating layer results in a relatively low programming voltage and a reduced resistance of a programmed BIC cell.

EXEMPLARY CLAIMS- 1. A programmable element for a semiconductor integrated circuit chip, comprising a lower electrode layer (34) formed on a substrate (35); a first insulating layer (31) formed on the lower electrode layer; and an upper electrode layer (36) formed on the first insulating layer, the upper electrode being separated from the lower electrode by the first insulating layer, whereby the programmable element is provided with a conduction path between the lower and upper electrodes when a voltage capable of causing an electrical breakdown in the first insulating layer is applied between the lower and upper electrodes, characterized in that said first insulating layer (31) is composed of at least two films (32, 33) of dielectric materials, successively formed on said lower electrode layer (34), said dielectric material films having respective specific dielectric constants different from each other.; 2. A programmable element according to claim 1, wherein one of said dielectric films is a silicon-nitride film (32).; 3. A programmable element according to any one of claims 1 and 2, wherein one of said dielectric films is a silicon-dioxide film (33).; 4. A programmable element according to any one of claims 1 to 3, wherein said first insulating layer comprises a relatively thin silicon-dioxide film (33) and a relatively thick silicon-nitride film (32).; 5. A programmable element according to any one of the preceding claims, wherein one of said dielectric films is a silicon-nitride film (32) having a thickness in a range from 5 nm to 20 nm.; 6. A programmable element according to any one of the preceding claims, wherein one of said dielectric films is a silicon-dioxide film (33) having a thickness in a range from 0.5 nm to 10 nm.

NO-DESCRIPTORS .

Citations from Engineering Index: EI1

14. Surface micromachined pressure transducers.

EIX 92-01 EIX92010003824 NDN- 017-0162-4540-3

AUTHORS- Guckel, H.

Sens Actuators A Phys v 28 n 2 Jul 1991 p 133-146

PUBLICATION DATE- 1991

DOCUMENT TYPE- JA, Journal Article

ISSN- 0924-4247

CODEN- SAAPEB

AUTHOR AFFILIATION- Univ of Wisconsin, Madison, WI, USA

MONTHLY PUBLICATION NUMBER- 010241

JOURNAL NAME- Sensors and Actuators, A: Physical
LANGUAGE- English

Typical IC processing is fundamentally two dimensional; sensors are three-dimensional structures. In surface micromachining, two-dimensional IC processing is extended to sensor structures by the addition of one or more sacrificial layers which are removed by lateral etching. The resulting sensor structures involve the substrate and one or more deposited films which form the intended micromechanical component. The concepts of this type of sensor manufacturing are readily demonstrated by considering absolute pressure transducers in some detail. Absolute pressure transducers involve a vacuum-sealed cavity and a deformation sensing technique. The cavity is formed from the substrate and a low-pressure chemical vapor deposited polycrystalline silicon film. The mechanical properties of this film must be controlled well enough to allow the device to be designed. This implies morphological control during processing. Optimized film's which do exhibit controlled compressive or tensile strains exclude oxygen or nitrogen and are therefore not modified by extended hydrofluoric acid etches. Their mechanical behavior is monitored by micromechanical test structures which measure Euler buckling and thereby determine the value of the built-in strain. The cavity vacuum is established by reactive sealing. Long-term vacuum integrity is achieved by a low-stress silicon nitride barrier which also acts as a dielectric isolation barrier. Sensing is accomplished via deposited polysilicon resistors. These devices behave like metal resistors in terms of their temperature coefficient of resistance and noise figure. Their piezoresistive behavior is larger than that of typical metal film structures and smaller than that of single-crystal resistors. Pressure sensors with four diaphragms, two active and two inactive, have been constructed and optimized towards manufacturability. The measured performance is excellent and agrees with the predictions of the design algorithm. (Author abstract) 40 Refs.

DESCRIPTOR- INTEGRATED CIRCUITS ; PIEZOELECTRIC TRANSDUCERS;
SEMICONDUCTING SILICON --Films; SENSORS

IDENTIFIER- MICROMACHINING; POLYSILICON

TREATMENT CODE- TC-X (Experimental); TC-T (Theoretical)

SECTIONAL CLASSIFICATION CODE- CAL944; CAL714; CAL712; CAL531; CAL933;
CAL704

SECTION HEADING- PRESSURE TRANSDUCERS --Performance

Citations from Engineering Index: EI2

15. Measurement of polyimide interlayer adhesion using microfabricated structures.

EIX 89-05 EIX89050045495 NDN- 163-0241-9685-5

AUTHORS- Allen, Mark G.; Senturia, Stephen D.

Polymeric Materials Science and Engineering, Proceedings of the ACS Division of Polymeric Materials Science and Engineering v 59. Publ by ACS, Books & Journals Division, Washington, DC, USA. p 352-356

PUBLICATION DATE- 1988

DOCUMENT TYPE- CA, Conference Paper

ISSN- 0743-0515

CODEN- PMSEDG

AUTHOR AFFILIATION- MIT, Cambridge, MA, USA

PATENT REFERENCE- Polymeric Materials Science and Engineering, Proceedings of the ACS Division of Polymeric Materials Science and Engineering

PATENT STATUS INFORMATION- 045536

CONFERENCE DATE- 19880926-19880930

CONFERENCE TITLE- Proceedings of the ACS Division of Polymeric Materials: Science and Engineering - Fall Meeting

CONFERENCE LOCATION- Los Angeles, CA, USA

LANGUAGE- English

The adhesion of polymer layers is extremely important in many integrated circuit multilevel metal interconnect schemes. Cracks between layers can result in moisture ingress and corrosion of metal lines, leading to long term device reliability problems. In addition, catastrophic delamination, (for example, induced by film stress) can result in the sudden and immediate failure of the device. In spite of the importance of interlayer adhesion, few tests are available which can measure quantitatively and in-situ the energy necessary to debond these films. Preliminary work has focused primarily on the peel test. However, the peel test suffers from two shortcomings which limit its utility. First, loading the sample is difficult; grasping one layer of film while keeping the others adhered can be a problem. Second, and most importantly, the peel test can be tensile strength limited. If the layers to be peeled apart are very thin and also well-adhered, tearing instead of interlayer debonding may occur. In this case, it is not possible to make a measurement of the debond energy of the film. The authors developed a modification of the standard blister test, called the 'island blister', which can overcome this tensile strength limit, as well as allow a convenient method of loading the film. The test and its application to the problem of polyimide interlayer adhesion are discussed in this paper. 12 Refs.

DESCRIPTOR- ADHESION --Testing; FILMS --Dielectric; INTEGRATED CIRCUITS -- Reliability

IDENTIFIER- BLISTER TEST; CATASTROPHIC DELAMINATION; FILM STRESS EFFECTS; INTEGRATED CIRCUIT MULTILEVEL METAL INTERCONNECT SCHEMES; MICROFABRICATED STRUCTURES; POLYIMIDE INTERLAYER ADHESION

TREATMENT CODE- TC-G (General Review); TC-X (Experimental)

SECTIONAL CLASSIFICATION CODE- CAL815; CAL817; CAL801; CAL931; CAL713; CAL714

SECTION HEADING- POLYIMIDES --Adhesion

Citations from INSPEC: IN2

16. Residual stress in PZT thin films and its effect on ferroelectric properties
INS 93-51 4565984 A9403-6860-003 (PHA) NDN- 083-0456-5984-0

AUTHORS- Garino, T. J.; Harrington, H. M.

EDITOR- Kingon, A. I.; Myers, E. R.; Tuttle, B.

ABBREVIATED JOURNAL TITLE- Ferroelectric Thin Films II Symposium

PUBLICATION DATE- 1992

PP 341-7

xvii+585 PAGES

16 REFERENCES

DOCUMENT TYPE- Conference paper

CORPORATE AUTHOR- Sandia Nat. Labs., Albuquerque, NM, USA

PUBLISHER- Mater. Res. Soc

PUBLICATION PLACE- Pittsburgh, PA, USA

PUBLICATION COUNTRY- USA

CONFERENCE DATE- 2-4 Dec. 1991

CONFERENCE LOCATION- Boston, MA, USA

LANGUAGE- English (DEF)

The residual stress in solution derived $Pb(Zr_{0.53}Ti_{0.47})O_3$, PZT 53:47, films was determined by measuring the bending of the substrate due to the stress. The substrate consisted of an oxidized (100) silicon wafer with 300 nm coating of platinum. In all cases the stress was tensile. Films fired at a temperature in the range where pyrochlore formation occurs (500 degrees to 575 degrees C) had the highest residual stresses, 200 to 350 MPa, whereas those fired at higher temperatures, 600 degrees to 650 degrees C, where the perovskite phase forms had stresses of 100 to 200 MPa. Stress measurements made during film firing indicate that the pyrochlore containing films had higher residual stress because their coefficient of thermal expansion was much larger than that of predominantly perovskite films. The effect of the amount of stress on ferroelectric properties was studied by making measurements on a film with and without the application of an external stress. The external stress was applied by bending a circular section of the substrate, which effectively lowered the amount of tensile stress in the film by -30%. Decreasing the stress in this manner was found to increase the remanent polarization by -11% and the dielectric constant by -2%.

DESCRIPTOR- dielectric polarisation; ferroelectric materials; ferroelectric thin films; internal stresses; lead compounds; permittivity; thermal expansion

IDENTIFIER- bending; dielectric constant; external stress; ferroelectric properties; film firing; perovskite phase; pyrochlore formation; remanent polarization; residual stress; substrate; tensile stress; thermal expansion; $Pb(Zr_{0.53}Ti_{0.47})O_3$; $PbZrO_3TiO_3$; Pt; PZT; PZT thin films; SiO_2 ; 500 to 650 degC

NUMERICAL DATA INDEXING- temperature 7.73E+02 to 9.23E+02 K

CHEMICAL INDEXING- $PbZrO_3TiO_3/_{ss} TiO_3/_{ss} ZrO_3/_{ss} O_3/_{ss} Pb/_{ss} Ti/_{ss} Zr/_{ss} O/_{ss}$; $Pt/sur Pt/el$; $SiO_2/sur O_2/sur Si/sur O/sur SiO_2/bin O_2/bin Si/bin O/bin$

TREATMENT CODE- TC-X

SECTIONAL CLASSIFICATION CODE- A6860; A7780; A7755; A7730; A7720; A6570

17. Stress and stress relaxation in integrated circuit metals and dielectrics

INS 91-24 4015570 B91076888 (EEA) NDN- 083-0401-5570-3

AUTHORS- Draper, B. L.; Hill, T. A.

JOURNAL NAME- Journal of Vacuum Science & Technology B (Microelectronics Processing and Phenomena)

ABBREVIATED JOURNAL TITLE- J. Vac. Sci. Technol. B, Microelectron. Process. Phenom. (USA)

VOLUME 9

NUMBER 4

PUBLICATION DATE- July-Aug. 1991

PP 1956-62

18 REFERENCES

DOCUMENT TYPE- Journal paper

ISSN- 0734-211X

CODEN- JVTBD9

CORPORATE AUTHOR- Sandia Nat. Labs., Albuquerque, NM, USA

COPYRIGHT CLEARANCE CENTER CODE- 0734-211X/91/041956-07\$01.00

PUBLICATION COUNTRY- USA

LANGUAGE- English (DEF)

In order to provide data needed in the investigation and modeling of stress voiding in integrated circuit metallizations, stress and stress relaxation in Al/Si/Cu alloys and common dielectrics were studied as a function of storage temperature and deposition conditions. It was found that the room-temperature tensile stress in Al/Si/Cu increases with increasing substrate bias and deposition temperature, and that the isothermal relaxation rate upon cooling from 400 degrees C is sharply dependent on temperature. The activation energy for the relaxation process was found to be 0.39 eV above 130 degrees C and about 0.08 eV at lower temperatures. For insulating layers deposited with plasma-enhanced chemical-vapor deposition techniques, strong correlations were found among stress, density, hydrogen content, deposition temperature, and film composition (oxides, nitrides, and several intermediate oxynitrides), with the highest levels of compressive stress (near 1 GPa) being measured in nitride films deposited at 300 degrees C. These films, as well as phosphorus-doped glasses used as capping/protection layers, were found to undergo structural changes upon post-deposition thermal cycling which affected stress levels.

DESCRIPTOR- aluminium alloys; copper alloys; dielectric thin films; internal stresses; metallisation; plasma CVD coatings; silicon alloys; stress relaxation

IDENTIFIER- activation energy; capping/protection layers; compressive stress; deposition conditions; deposition temperature; integrated circuit metals; isothermal relaxation rate; metallizations; nitride films; plasma-enhanced chemical-vapor deposition techniques; post-deposition thermal cycling; room-temperature tensile stress; storage temperature; stress relaxation; stress voiding; substrate bias; AlSiCu; 0.08 to 0.39 eV

NUMERICAL DATA INDEXING- electron volt energy 8.0E-02 to 3.9E-01 eV

CHEMICAL INDEXING- AlSiCu/int Al/int Cu/int Si/int AlSiCu/ss Al/ss Cu/ss Si/ss

TREATMENT CODE- TC-P; TC-X

SECTIONAL CLASSIFICATION CODE- B2550F; B0520F; B2550E

18. Properties of a photoimageable thin polyimide film

INS 91-22 4000730 B91067960 (EEA) NDN- 083-0400-0730-0

AUTHORS- Maw, T.; Hopla, R. E.

EDITOR- Lillie, E. D.; Ho, P. S.; Jaccodine, R.; Jackson, K.

ABBREVIATED JOURNAL TITLE- Electronic Packaging Materials Science V.

Symposium

PUBLICATION DATE- 1991

PP 71-6

xiii+455 PAGES

5 REFERENCES

DOCUMENT TYPE- Conference paper

CORPORATE AUTHOR- Ciba-Geigy Corp., Ardsley, NY, USA

SPONSORING AGENCY- Mater. Res. Soc

PUBLISHER- Mater. Res. Soc

PUBLICATION PLACE- Pittsburgh, PA, USA

PUBLICATION COUNTRY- USA

CONFERENCE DATE- 26-29 Nov. 1990

CONFERENCE LOCATION- Boston, MA, USA

LANGUAGE- English (DEF)

Mechanical properties (tensile modulus, tensile strength, elongation at break), thermal properties (T_g, CTE, thermo-decomposition temperature, and rate of weight loss) and electrical properties of Probimide 414 cured films have been determined. The mechanical properties of Probimide 414 thin films are highly dependent on the hard-bake temperature, hard-bake time and purge gas, but not dependent on the level of the exposure energy or the presence of 1% Irganox 1010 (w/w) as a stabilizer. At a hard-bake temperature of 350 degrees C and a nitrogen purge rate of 15 SCFH, Probimide 414 films showed excellent retention of the mechanical properties during extended heat treatment.

DESCRIPTOR- elongation; glass transition (polymers); heat treatment; integrated circuit technology; packaging; permittivity; polymer films; pyrolysis; tensile strength; thermal expansion

IDENTIFIER- dielectric constant; electrical properties; elongation; exposure energy; extended heat treatment; glass transition temperature; hard-bake temperature; hard-bake time; integrated circuits; mechanical properties; packaging; photoimageable thin polyimide film; stabilizer; tensile modulus; tensile strength; thermal properties; thermo-decomposition temperature; weight loss rate; CTE; Irganox 1010; N₂ purge gas; Probimide 414 cured films; 0.5 to 14 hours; 15 SCFH films; 350 degC

NUMERICAL DATA INDEXING- temperature 6.23E+02 K; time 1.8E+03 to 5.0E+04 s

CHEMICAL INDEXING- N₂ el N el

TREATMENT CODE- TC-X

SECTIONAL CLASSIFICATION CODE- B0560; B0170J; B2810; B2570

19. Control of thin film materials properties used in high density multichip interconnect

INS 90-04 3743142 B90069319 (EEA) NDN- 083-0374-3142-2

AUTHORS- Reche, J. J. H.

EDITOR- Jaccodine, R.; Jackson, K. A.; Lillie, E. D.; Sundahl, R. C.

ABBREVIATED JOURNAL TITLE- Electronic Packaging Materials Science IV.

Symposium

PUBLICATION DATE- 1989

PP 39-46

xiii+494 PAGES

39 REFERENCES

DOCUMENT TYPE- Conference paper

CORPORATE AUTHOR- Polycon, Ventura, CA, USA

SPONSORING AGENCY- Army Res. Office; Allied-Signal Corp.; Amoco; Dow; Intel; Office Naval Res

PUBLISHER- Mater. Res. Soc

PUBLICATION PLACE- Pittsburgh, PA, USA

PUBLICATION COUNTRY- USA

CONFERENCE DATE- 24-28 April 1989

CONFERENCE LOCATION- San Diego, CA, USA

LANGUAGE- English (DEF)

Most literature on high density multichip interconnect (HDMI) focuses almost exclusively on processing of the organic dielectric. Nevertheless, it is only one of the components in high density multichip modules. Substrate properties, metal dielectric adhesion, internal stresses in the various films, and many other physico-chemical properties of the materials, can all be affected by neighbouring layers or process parameters improperly identified. Thus, in the course of process development, the real causes of difficulties and observed phenomena can easily be misconstrued. The paper reviews some of the relationships between the properties of the thin film metallization and their effects on the dielectric layers. It also points out to some of the difficulties that can occur when treating the dielectric and the metallic layers as separate issues.

DESCRIPTOR- adhesion; integrated circuit technology; internal stresses; metallisation; packaging; polymer films; reviews

IDENTIFIER- adhesion; dielectric layers; high density multichip interconnect; high density multichip modules; internal stresses; metal dielectric adhesion; physico-chemical properties; polyimide film; process parameters; substrate properties; tensile stress; thin film material properties control; thin film metallization; HDMI

TREATMENT CODE- TC-G; TC-P

SECTIONAL CLASSIFICATION CODE- B2550F; B2570; B0170J

Citations from INSPEC (80-89): IN3

20. Metallized MIC substrates using high K dielectric resonator materials
INS 89-01 3312580 B89015238 (EEA) NDN- 161-0331-2580-8

AUTHORS- Tamura, H.; Nishikawa, T.; Wakino, K.; Sudo, T.

JOURNAL NAME- Microwave Journal

ABBREVIATED JOURNAL TITLE- Microw. J. (USA)

VOLUME 31

NUMBER 10

PUBLICATION DATE- Oct. 1988

PP 117-18, 120, 122, 124, 126

3 REFERENCES

DOCUMENT TYPE- Journal paper

ISSN- 0026-2897

CODEN- MCWJAD

CORPORATE AUTHOR- Murata Manuf. Co. Ltd., Kyoto, Japan

PUBLICATION COUNTRY- USA

LANGUAGE- English (DEF)

The authors describe newly developed metallised substrates using high permittivity dielectric resonator materials. Their pore sizes were reduced to 2 μ m average and 5 μ m maximum so that they could be covered with high resolution circuit patterns. Compared with thin-film alumina substrates, they have the following advantages and disadvantages. The advantages are as follows: since they have higher dielectric constants, circuits utilizing electric length elements (such as stubs or filters) are miniaturized; and as they have a temperature coefficient of 0 p.p.m./ degrees C, temperature-stable microstrip line filters can be constructed directly on the substrate. The disadvantages are as follows: thermal conductivity of these materials is 10 times smaller than that of alumina; they have flexural strength 50 to 70

percent that of alumina; and they are expensive since they need surface polishing. Other characteristics (such as surface roughness, pore size and distribution, tensile strength between substrate and metallised electrode, and thickness of metallisation) are comparable to those of alumina substrates.

DESCRIPTOR- ceramics; dielectric materials; dielectric resonators; integrated circuit technology; metallisation; microwave integrated circuits ; substrates; thin film circuits

IDENTIFIER- ceramics; dielectric resonator materials; high permittivity; high resolution circuit patterns; high K; metallised substrates; microstrip line filters; microwave IC; pore sizes; thermal conductivity; thin film circuits; BaO; BaO-PbO-Nd/sub 2/O/sub 3/-TiO/sub 2/; MIC substrates; Nd/sub 2/O/sub 3/; PbO; TiO/sub 2/; ZrSnTiO/sub 4/; 2 to 5 micron

NUMERICAL DATA INDEXING- size 2.0E-06 to 5.0E-06 m

CHEMICAL INDEXING- ZrSnTiO₄/ss O₄/ss Sn/ss Ti/ss Zr/ss O/ss; BaOPbONd₂O₃TiO₂/ss Nd₂/ss Ba/ss Nd/ss O₂/ss O₃/ss Pb/ss Ti/ss O/ss; TiO₂/bin O₂/bin Ti/bin O/bin; BaO/bin Ba/bin O/bin; PbO/bin Pb/bin O/bin; Nd₂O₃/bin Nd₂/bin Nd/bin O₃/bin O/bin

TREATMENT CODE- TC-P

SECTIONAL CLASSIFICATION CODE- B1350F; B2220E; B2810; B2890; B0540

21. Stresses in borophosphosilicate glass films during thermal cycling

INS 89-00 3279154 A88141344 (PHA); B89002629 (EEA) NDN- 161-0327-9154-3

AUTHORS- Townsend, P. H.; Huggins, R. A.

EDITOR- Rothman, L. B.; Herndon, T.

ABBREVIATED JOURNAL TITLE- Proceedings of the Symposium on Multilevel Metallization, Interconnection, and Contact Technologies

PUBLICATION DATE- 1987

PP 134-41

vii+272 PAGES

6 REFERENCES

DOCUMENT TYPE- Conference paper

CORPORATE AUTHOR- Dept. of Mater. Sci. & Eng., Stanford Univ., CA, USA

PUBLISHER- Electrochem. Soc

PUBLICATION PLACE- Pennington, NJ, USA

PUBLICATION COUNTRY- USA

CONFERENCE DATE- 21-22 Oct. 1986

CONFERENCE LOCATION- San Diego, CA, USA

LANGUAGE- English (DEF)

Stresses in thin films of borophosphosilicate glass deposited by atmospheric pressure CVD were measured during thermal cycling. Films of two different doping concentrations were examined for their flow properties. Initial heating produces an increase in the tensile stress as a consequence of film densification. Further heating leads to a decrease in the stress level as a result of plastic flow in the film. The addition of boron to PSG increases the tendency of the films to undergo plastic flow at elevated temperatures. Constant temperature flow behavior between 500 degrees C and 700 degrees C was nonlinear. The activation energy for plastic flow was found to be 150 kcal/mole (6.5 eV/particle).

DESCRIPTOR- borosilicate glasses; heat treatment; insulating thin films; metallisation; phosphosilicate glasses; plastic flow; thermal stresses; CVD coatings

IDENTIFIER- activation energy; atmospheric pressure CVD; constant temperature flow; doping concentrations; film densification; flow properties; glass films; heating; insulating dielectric layer; nonlinear behaviour; plastic flow; tensile stress; thermal cycling; BPSG; B2O3-P2O5-SiO2; IC metallisation; 500 to 700 degC
NUMERICAL DATA INDEXING- temperature 7.73E+02 to 9.73E+02 K
CHEMICAL INDEXING- B2O3-P2O5-SiO2/int B2O3/int P2O5/int SiO2/int B2/int O2/int O3/int O5/int P2/int Si/int B/int O/int P/int B2O3/bin P2O5/bin SiO2/bin B2/bin O2/bin O3/bin O5/bin P2/bin Si/bin B/bin O/bin P/bin
TREATMENT CODE- TC-X
SECTIONAL CLASSIFICATION CODE- A8140G; A6860; A8140L; A6220F; B2830E; B2550F; B2810

22. Low stress films of cyclized polybutadiene dielectrics by vacuum annealing
INS 89-00 3279151 B89001989 (EEA) NDN- 161-0327-9151-9

AUTHORS- Salazar, M.; Wilkins, C. W., Jr.; Ryan, V. W.; Wang, T. T.

EDITOR- Rothman, L. B.; Herndon, T.

ABBREVIATED JOURNAL TITLE- Proceedings of the Symposium on Multilevel Metallization, Interconnection, and Contact Technologies

PUBLICATION DATE- 1987

PP 96-102

vii+272 PAGES

7 REFERENCES

DOCUMENT TYPE- Conference paper

CORPORATE AUTHOR- AT&T Bell Labs., Murray Hill, NJ, USA

PUBLISHER- Electrochem. Soc

PUBLICATION PLACE- Pennington, NJ, USA

PUBLICATION COUNTRY- USA

CONFERENCE DATE- 21-22 Oct. 1986

CONFERENCE LOCATION- San Diego, CA, USA

LANGUAGE- English (DEF)

The authors report a vacuum annealing technique for the post-deposition processing of cyclized polybutadiene dielectric (CBR) films. The technique has proven effective in reducing film stress from $3.1+0r-0.5*10^{sup} 8/$ dynes/cm/² (tensile) to $1.4+0r-0.2*10^{sup} 8/$ dynes/cm/² when the material is thermally cycled between 20 and 280 degrees C. For 10 μ m thick films the technique results in a net reduction in Si wafer bow by a factor of two. This reduction in wafer bow is important in the building of multilevel metallization structures where problems with patterning of films and automatic wafer handling equipment are encountered with excessively bowed substrates. A change in the glass transition temperature from approximately 320 to approximately 130 degrees C was also observed in the vacuum treated films and mechanical coupling to the substrate was seen to occur at approximately 175 degrees C instead of 280 degrees C.

DESCRIPTOR- annealing; dielectric thin films; integrated circuit technology; metallisation; polymer films

IDENTIFIER- cyclized polybutadiene dielectrics; film stress reduction; glass transition temperature; low stress polymer films; mechanical coupling; multilevel metallization structures; post-deposition processing; thermal cycling; vacuum annealing; vacuum treated films; IC technology; Si wafer bow reduction; 10 micron; 20 to 280 degC

NUMERICAL DATA INDEXING- temperature 2.93E+02 to 5.53E+02 K; size 1.0E-05 m

CHEMICAL INDEXING- Si/sur Si/el

TREATMENT CODE- TC-P; TC-X

SECTIONAL CLASSIFICATION CODE- B2550F; B2810; B2830C; B0560

23. Passivation of GaAs FET's with PECVD silicon nitride films of different stress states

INS 88-04 3252065 B88071823 (EEA) NDN- 161-0325-2065-2

AUTHORS- Chang, E. Y.; Cibuzar, G. T.; Pande, K. P.

JOURNAL NAME- IEEE Transactions on Electron Devices

ABBREVIATED JOURNAL TITLE- IEEE Trans. Electron Devices (USA)

VOLUME 35

VOLUME 33
NUMBER 9

NUMBER 3
PUBLICATION DATE- Sept 1988

PUBLICATION

PP 1412-18

PP 1412-18
12 REFERENCES

12 REFERENCES

DOCUMENT TYPE:
ISSN- 0018-9383

ISSN- 0018-938
CODEN- JETRAI

CODEN-IEIDAI
CORPORATE AUTHOR: Unisys Corp., St. Paul, MN, USA

CORPORATE AUTHOR- Unisys Corp., St. Paul, MN, USA
COPYRIGHT CLEARANCE CENTER CODE: 0018-0383/88/0202-1413\$1.00

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PUBLICATIONS DIVISION, U.S.A.

PUBLICATION COUNTRY- (Language- English (REF))

LANGUAGE- English (DEF)
The passivation of GaAs MESFETs with plasma-enhanced chemical-vapor-deposited (PECVD) silicon nitride films of both compressive and tensile stress is reported.

(PECVD) silicon nitride films of both compressive and tensile stress is reported. Elastic stresses included in GaAs following nitride passivation can produce piezoelectric charge density, which results in a shift of MESFET characteristics. The

piezoelectric charge density, which results in a shift of MESFET characteristics. The shift of MESFET parameters due to passivation was found to be dependent on gate orientation. The experiments show that nitride of tensile stress is preferable for MESFETs with (011-bar) oriented gates. The shifts in V_{TH} , I_{DSS} , and G/M of the devices before and after nitride passivation are less than 5% if the nitride of appropriate stress states are used for passivation. The breakdown voltage of the MESFETs after nitride deposition was also studied. It is found that the process with higher hydrogen incorporation tends to reduce the surface oxide and increase the breakdown voltage after nitride deposition. In addition, the passivation of double-channel HEMTs is reported for the first time.

DESCRIPTOR- dielectric thin films; electric breakdown of solids; field effect integrated circuits ; gallium arsenide; high electron mobility transistors; integrated circuit technology; microwave integrated circuits ; passivation; semiconductor technology; silicon compounds; stress effects; CVD coatings; III-V semiconductors; Schottky gate field effect transistors

IDENTIFIER- breakdown voltage; characteristics shift; compressive stress; double-channel HEMTs; elastic stresses; gate orientation; microwave IC; monolithic IC; nitride passivation; piezoelectric charge density; plasma-enhanced chemical-vapor-deposited; surface oxide reduction; tensile stress; CVD coating; GaAs; H incorporation; III-V semiconductors; MESFETs; MMIC; PECVD; Si₃N₄

CHEMICAL INDEXING- Si3N4/int Si3/int N4/int Si/int N/int Si3N4/bin Si3/bin N4/bin Si/bin N/bin; H/el; GaAs/int As/int Ga/int GaAs/bin As/bin Ga/bin

TREATMENT CODE- TC-X

SECTIONAL CLASSIFICATION CODE- B0520F; B1350F; B2550E; B2560S; B2570H

24. Characterization of a spin-applied dielectric for use in multilevel metallization
INS 88-03 3213789 B88057504 (EEA) NDN- 161-0321-3789-5

AUTHORS- Riley, P. E.; Shelley, A.

JOURNAL NAME- Journal of the Electrochemical Society

ABBREVIATED JOURNAL TITLE- J. Electrochem. Soc. (USA)

VOLUME 135

NUMBER 5

PUBLICATION DATE- May 1988

PP 1207-10

25 REFERENCES

DOCUMENT TYPE- Journal paper

ISSN- 0013-4651

CODEN- JESOAN

CORPORATE AUTHOR- Fairchild Res. Center, Palo Alto, CA, USA

PUBLICATION COUNTRY- USA

LANGUAGE- English (DEF)

The spin-applied polysiloxane film Futurrex ICI-200 has been examined for use as a planarizing component of the dielectric layers of high density integrated circuits utilizing multiple levels of interconnecting metallization. The thickness of the as-spun film varies significantly with cure: it is invariant after thermal curing at 190 degrees C in vacuo or 250 degrees C in air and after additional curing at 450 degrees C in N₂ or Ar. However, the index of refraction decreases from 1.414 after curing at 190 degrees C to 1.340 after curing at 450 degrees C in either inert ambient.

Treatment of the thermally cured films (190 degrees or 450 degrees C) with an O₂ plasma for 30 min in a barrel reactor results in a decrease in thickness of approximately 40% and a concomitant increase in the index of refraction from 1.414 to 1.438. Despite this large reduction in thickness, the stress of the film is low (1.7*10¹⁰ dyn/cm², tensile) after O₂-plasma curing. Etch rates of the thermally and O₂-plasma cured films in HF and P-etch solutions suggest that the organosilicon material becomes porous and inorganic-like after exposure to the O₂ plasma in a barrel reactor. This is supported by the Fourier transform infrared (FTIR) spectra of the material; after curing in an O₂ plasma the band assigned to CH₃ substituents of the polysiloxane is absent, while a band at 1060 cm⁻¹, which is close to the position of the Si-O-Si stretching vibration in SiO₂, sharpens and increases in intensity. In addition, although the FTIR spectra of the films cured at 190 degrees C in vacuo or at 450 degrees C in N₂ are featureless from 3100 to 3600 cm⁻¹, that of the O₂-cured film exhibits a small, broad absorption in this region, suggestive of the presence of absorbed water or the formation by hydrolysis of Si-OH moieties in this apparently more porous framework.

DESCRIPTOR- dielectric thin films; infrared spectra of organic molecules and substances; integrated circuit technology; metallisation; polymer films; refractive index

IDENTIFIER- absorbed water; as-spun film; barrel reactor; dielectric; etch rates; high density integrated circuits ; hydrolysis; index of refraction; multilevel metallization; organosilicon material; planarization; polysiloxane; porous; stress; stretching vibration; thermal curing; thickness; Futurrex ICI-200; FTIR spectra; O₂ plasma

CHEMICAL INDEXING- O₂/el O/el

TREATMENT CODE- TC-X
SECTIONAL CLASSIFICATION CODE- B2550F; B2570

25. Material characteristics of spin-on glasses for interlayer dielectric applications
INS 88-01 3111185 A88044772 (PHA); B88026019 (EEA) NDN- 161-0311-
1185-9

AUTHORS- Pei-lin Pai; Chetty, A.; Roat, R.; Cox, N.; Chiu Ting

JOURNAL NAME- Journal of the Electrochemical Society

ABBREVIATED JOURNAL TITLE- J. Electrochem. Soc. (USA)

VOLUME 134

NUMBER 11

PUBLICATION DATE- Nov. 1987

PP 2829-34

16 REFERENCES

DOCUMENT TYPE- Journal paper

ISSN- 0013-4651

CODEN- JESOAN

CORPORATE AUTHOR- Intel Corp., Components Res., Santa Clara, CA, USA
PUBLICATION COUNTRY- USA

LANGUAGE- English (DEF)

The material properties of several commercial spin-on glasses were investigated. Infrared spectrophotometry was used to study the annealing effects on the contents of hydroxyl and organic groups. Their concentrations are found to be sensitive to the annealing temperatures and annealing ambients. Both the room-temperature stress and the in situ stress during annealing were monitored. The measured stress levels of films on Si wafers are low (less than 10⁸ Pa in tensile) compared to other deposited silicon dioxide films. Dielectric properties, including dielectric constants and dissipation factors, were also examined as a function of annealing conditions. A strong correlation between the dielectric properties and the OH content in the film was established. Of the two films studied most extensively, one showed significantly better dielectric properties following low-temperature (<600 degrees C) curing. Both are good dielectric films for VLSI interlayer dielectric applications if high-temperature annealings are allowed.

DESCRIPTOR- annealing; dielectric thin films; glass; infrared spectra of inorganic solids; internal stresses; permittivity; semiconductor technology

IDENTIFIER- annealing; curing; dielectric constants; dissipation factors; films; infrared spectrophotometry; spin-on glasses; stress; Si wafers; VLSI interlayer dielectric

CHEMICAL INDEXING- Si/sur Si/el

TREATMENT CODE- TC-X

SECTIONAL CLASSIFICATION CODE- A6140D; A6855; A7755; B0570; B2550;
B2810

26. Stress measurements on multilevel thin film dielectric layers used in Si integrated circuits

INS 86-03 2753176 A86112945 (PHA); B86063194 (EEA) NDN- 161-0275-
3176-3

AUTHORS- Chen, Y. S.; Fatemi, H.

JOURNAL NAME- Journal of Vacuum Science & Technology A (Vacuum, Surfaces, and Films)

ABBREVIATED JOURNAL TITLE- J. Vac. Sci. Technol. A, Vac. Surf. Films (USA)

pt.1

VOLUME 4

NUMBER 3

PUBLICATION DATE- May-June 1986

PP 645-9

10 REFERENCES

DOCUMENT TYPE- Conference paper

ISSN- 0734-2101

CODEN- JVTAD6

CORPORATE AUTHOR- Adv. Mater. Res. Group, Adv. Micro Devices Inc., Santa Clara, CA, USA

COPYRIGHT CLEARANCE CENTER CODE- 0734-2101/86/030645-05\$01.00

PUBLICATION COUNTRY- USA

CONFERENCE DATE- 19-22 Nov. 1985

CONFERENCE TITLE- Proceedings of the 32nd National Symposium of the American Vacuum Society

CONFERENCE LOCATION- Houston, TX, USA

LANGUAGE- English (DEF)

Thin film induced stresses on a silicon substrate measured at room temperature, using a stress gauge wafer deflection setup. The thermal oxide was in high compressive stress due to CTE mismatch between oxide and Si substrate. As deposited PSG was in tensile stress decreasing in stress level with increasing P content. After densification, stress was reversed to the compressive mode with no significant reduction in stress for 8%-10% phosphorus content. As deposited poly-Si was in the high compressive mode. However, subsequent doping reduced the stress to one-half of 'as deposited' level and after annealing at 1000 degrees C the stress was further reduced. Cold sputtered aluminium metallization doped with 1% Si was found in the compressive mode, while hot sputtered copper doped Al metallization was under tension. Both films annealed at 450 degrees C hydrogen ambient exhibit reduced compressive and tensile levels, respectively. The CVD P-glass passivation was under low compression while plasma nitride was in high compressive stress. Most of these observations confirm previous reports. However, referenced results are confirmed and additional measurements are performed using a relatively new detection gauge system.

DESCRIPTOR- dielectric thin films; integrated circuit technology; internal stresses; passivation

IDENTIFIER- annealing; densification; doping; multilevel thin film dielectric layers; passivation; phosphosilicate glass; plasma nitride; poly-Si; polycrystalline Si; semiconductors; sputtered aluminium metallization; stress gauge wafer deflection setup; thermal oxide; thin film induced stresses; Al; Al-Cu; Al-Si; PSG; Si integrated circuits ; Si₃N₄; SiO₂/

TREATMENT CODE- TC-X

SECTIONAL CLASSIFICATION CODE- A6860; B2550E; B2570

27. Laser photolytic deposition of thin films

INS 83-03 2127483 A83103064 (PHA); B83053456 (EEA) NDN- 161-0212-

7483-2

AUTHORS- Boyer, P. K.; Moore, C. A.; Solanki, R.; Ritchie, W. K.; Roche, G. A.; Collins, G. J.

EDITOR- Osgood, R. M.; Brueck, S. R. J.; Schlossberg, H. R.

ABBREVIATED JOURNAL TITLE- Laser Diagnostics and Photochemical Processing for Semiconductor Devices. Proceedings of a Symposium

PUBLICATION DATE- 1983

PP 119-27

xiii+298 PAGES

8 REFERENCES

DOCUMENT TYPE- Conference paper

ISBN- 0 444 00782 2

CORPORATE AUTHOR- Dept. of Electrical Engng., Colorado State Univ., Fort Collins, CO, USA

SPONSORING AGENCY- Air Force Office Sci. Res

PUBLISHER- North-Holland

PUBLICATION PLACE- New York, NY, USA

PUBLICATION COUNTRY- USA

CONFERENCE DATE- Nov. 1982

CONFERENCE LOCATION- Boston, MA, USA

LANGUAGE- English (DEF)

An excimer laser is used to photochemically deposit thin films of silicon dioxide, silicon nitride, aluminium oxide, and zinc oxide at low temperatures (100-350 degrees C). Deposition rates in excess of 3000 Å/min and conformal coverage over vertical walled steps were demonstrated. The films exhibit low defect density and high breakdown voltage and have been characterized using IR spectrophotometry, AES, and C-V analysis. Device compatibility has been studied by using photodeposited films as interlayer dielectrics, diffusion masks, and passivation layers in production CMOS devices. Additionally, the authors have deposited metallic films of Al, Mo, W, and Cr over large (>5 cm²) areas using UV photodissociation of trimethylaluminium and the refractory metal hexacarbonyls. Both shiny metallic films as well as black particulate films were obtained depending on the deposition geometry. The black films are shown to grow in columnar grains. The depositions were made at room temperature over pyrex and quartz plates as well as silicon wafers. The authors have examined the resistivity, adhesion, stress and step coverage of these films. The films exhibited resistivities at most approximately 20 times that of the bulk materials and tensile stress no higher than 7×10^9 dynes/cm².

DESCRIPTOR- alumina; aluminium; chemical vapour deposition; chromium; insulating thin films; laser beam applications; metallic thin films; molybdenum; silicon compounds; tungsten; zinc compounds

IDENTIFIER- adhesion; black particulate films; columnar grains; device compatibility; diffusion masks; high breakdown voltage; interlayer dielectrics; laser pyrolytic deposition; low defect density; metallic films; passivation layers; photochemically deposit; photodeposited films; production CMOS devices; resistivity; step coverage; stress; tensile stress; thin films; vertical walled steps; Al; Al₂O₃; AES; C-V analysis; Cr; IR spectrophotometry; Mo; Si₃N₄; SiO₂; UV photodissociation; W; ZnO

TREATMENT CODE- TC-P; TC-X

SECTIONAL CLASSIFICATION CODE- A6855; A8115H; B0520F; B2550F; B2550G; B4360

28. Low temperature double-exposed polyimide/oxide dielectric for VLSI multilevel metal interconnection
INS 83-01 2017251 B83018518 (EEA) NDN- 161-0201-7251-6

AUTHORS- Wade, T. E.

JOURNAL NAME- IEEE Transactions on Components, Hybrids, and Manufacturing Technology

ABBREVIATED JOURNAL TITLE- IEEE Trans. Compon. Hybrids Manuf. Technol. (USA)

VOLUME CHMT-5

NUMBER 4

PUBLICATION DATE- 1982

PP 516-19

12 REFERENCES

DOCUMENT TYPE- Journal paper

ISSN- 0148-6411

CODEN- ITTEDR

CORPORATE AUTHOR- Microelectronics Res. Lab., Mississippi State Univ., Mississippi State, MS, USA

COPYRIGHT CLEARANCE CENTER CODE- 0148-6411/82/1200-0516\$00.75

PUBLICATION COUNTRY- USA

LANGUAGE- English (DEF)

By use of a double-exposed (double-etch) low temperature polyimide/oxide process, the packing density for both first and second level metal interconnection can be improved by some 35 percent and 30 percent, respectively, in the vicinity of the via. Moreover, the complete interconnect process may be realized at temperatures below 300 degrees C. Since polyimide can be applied in thick layers having negligible (tensile) stress, a planar surface results and also parasitic lead capacitances may be considerably reduced. This process is also amenable to either wet chemical or dry plasma processing.

DESCRIPTOR- dielectric thin films; integrated circuit technology; large scale integration; polymer films

IDENTIFIER- double-exposed polyimide/oxide dielectric; dry plasma processing; interconnect process; packing density; parasitic lead capacitances; planar surface; via; wet chemical processing; VLSI multilevel metal interconnection

TREATMENT CODE- TC-A; TC-P

SECTIONAL CLASSIFICATION CODE- B2550E; B2570

Citations from INSPEC (69-79): IN4

29. A switching plate with aluminium membrane crossings of conductors
INS 73-00 506162 B73016463 (EEA) NDN- 082-0050-6162-5

AUTHORS- Svechnikov, S. V.; Kobylyatskaya, M. F.; Kimarskii, V. I.; Kaufman, A. P.; Kuzovlev, Yu. I.; Cherepov, Ye. I.; Fomin, B. I.

JOURNAL NAME- Poluprovodnikovaya Tekhnika i Mikroelektronika

ABBREVIATED JOURNAL TITLE- Poluprovodn. Tekh. Mikroelektron. (Ukrainian SSR)

NUMBER 10

PUBLICATION DATE- 1972

PP 70-3

5 REFERENCES

DOCUMENT TYPE- Journal paper

ISSN- 0554-6222

CODEN- PTMUAC

PUBLICATION COUNTRY- Ukrainian SSR, USSR

LANGUAGE- Russian

Describes a switching plate for monocrystalline integrated circuits, possessing a large number of interconnections, crossings and contacting areas; it is made in a three-layer form, using only two metals, aluminium and vanadium. The crossings possess a two-layer dielectric insulation, the upper layer being a thin diaphragm, fixed in tension on two stops. The contacting areas facilitate the junctions with beam-lead integrated circuits. In another form junctions are made by a reverse-crystal method using ultrasonic welding of aluminium with aluminium.

DESCRIPTOR- aluminium; conductors (electric); integrated circuits ; metallic thin films

IDENTIFIER- contacting areas; crossings; interconnections; monocrystalline integrated circuits ; switching plate; Al membrane crossings

TREATMENT CODE- TC-X

SECTIONAL CLASSIFICATION CODE- B2110; B2220; B2570

30. Internal stresses and resistivity of low-voltage sputtered tungsten films
(microelectronic cct. conductor)

INS 73-00 505840 A73024515 (PHA); B73016101 (EEA) NDN- 082-0050-5840-
7

AUTHORS- Sun, R. C.; Tisone, T. C.; Cruzan, P. D.

JOURNAL NAME- Journal of Applied Physics

ABBREVIATED JOURNAL TITLE- J. Appl. Phys. (USA)

VOLUME 44

NUMBER 3

PUBLICATION DATE- March 1973

PP 1009-16

DOCUMENT TYPE- Journal paper

ISSN- 0021-8979

CODEN- JAPIAU

CORPORATE AUTHOR- Bell Telephone Labs., Allentown, PA, USA

PUBLICATION COUNTRY- USA

LANGUAGE- English (DEF)

The continuing development of microelectronic circuits toward greater complexity has stimulated interest in new materials and processes compatible with the currently known silicon device technology. Tungsten has been considered as the first-level conductor for a multilevel structure due to its relatively low electrical resistivity, its thermal expansion coefficient which matches fairly well to that of silicon, its demonstrated good adherence to the dielectrics of interest, and its ability to withstand high-temperature processing. The present work is a part of a study of the dependence of the properties of low-voltage triode sputtered tungsten films upon deposition parameters. The electrical resistivity was observed to increase with increasing deposition rate, decreasing film thickness, and decreasing substrate

temperature. The internal stress was determined by two X-ray methods and in general, depending upon the deposition conditions, tensile or compressive stresses of the order 10^{sup} 9/-10^{sup} 10/ dyn/cm^{sup} 2/ were observed.

DESCRIPTOR- integrated circuits ; internal stresses; metal-insulator-semiconductor structures; metallic thin films; resistance (electric); sputtering; tungsten
IDENTIFIER- compressive stresses; compressive stresses; conductor; dielectrics; electrical resistivity; electron microprobe; internal stresses; lattice parameter; low voltage sputtered W film; microelectronic circuits; microstructure; multilevel structure; resistivity; silicon device technology; substrate temperature; tensile stress; thermal expansion coefficient; two exposure technique; W film

TREATMENT CODE- TC-X

SECTIONAL CLASSIFICATION CODE- A7340Q; B2110; B2220; B2530F; B2570

31. An evaluation of methods for passivating silicon integrated circuits

INS 72-01 392832 B72019249 (EEA) NDN- 082-0039-2832-0

AUTHORS- Jones, R. E., Jr.

JOURNAL NAME- Insulation/Circuits

ABBREVIATED JOURNAL TITLE- Insul./Circuits (USA)

VOLUME 18

NUMBER 4

PUBLICATION DATE- April 1972

PP 23-8

22 REFERENCES

DOCUMENT TYPE- Journal paper

ISSN- 0020-4544

CODEN- ISCUBF

CORPORATE AUTHOR- IBM Corp., San Jose, CA, USA

PUBLICATION COUNTRY- USA

LANGUAGE- English (DEF)

Emphasis is on the need for additional insulating layers on the surface to isolate lines of conductors which cross over on the way to output terminals. Criteria for film selection are outlined.

DESCRIPTOR- insulation; integrated circuits ; semiconductor materials

IDENTIFIER- adhesion; cracks; degradation; dielectric constant; etching; glass; grain structure; low ion mobility; n-type; p-type; passivating silicon integrated circuits ; pinholes; resistivity; stability; tensile stresses; transistor characteristics

TREATMENT CODE- TC-G

SECTIONAL CLASSIFICATION CODE- B2220; B2570

Citations from WORLD PATENT FULLTEXT: PC2

32. MULTICHIP INTEGRATED CIRCUIT MODULE AND METHOD OF FABRICATION, -

1992017901/WO-A1/

PCN 1992-10-15 1992017901/WO-A1 NDN- 052-0140-0809-9

INVENTOR- EICHELBERGER, Charles, W.
DATE FILED- 1992-03-26
PUBLICATION NUMBER- 1992017901/WO-A1
DOCUMENT TYPE- A1
PUBLICATION DATE- 1992-10-15
INTERNATIONAL PATENT CLASS- H01L02156; *H01L02328; *H01L02302
PATENT REFERENCE- 62122258/JP-A; 63293965/JP-A; 4630096/JP-A; 4860166/US-A; 5049980/US-A; 5065282/US-A
PCT APPLICATION NUMBER- 09202623/US
PATENT APPLICATION PRIORITY- 676,937
PRIORITY COUNTRY CODE- US
PRIORITY DATE- 1991-03-27
APPLICANT- INTEGRATED SYSTEM ASSEMBLIES CORPORATION
PUBLICATION COUNTRY- WO
DESIGNATED COUNTRY- AT; AU; BE; CA; CH; DE; DK; ES; FR; GB; GR; IT; JP; KR; LU; MC; NL; SE
A multichip integrated circuit package comprises a substrate (12) having a flat upper surface to which is affixed one or more integrated circuit chips (14) having interconnection pads (22). A polymer encapsulant (18) completely surrounds the integrated circuit chips (14). The encapsulant is provided with a plurality of via openings therein to accommodate a layer of interconnection metallization (20). The metallization (20) serves to connect various chips (14) and chip pads (22) with the interconnection pads (22) disposed on the chips (14). In specific embodiments, the module is constructed to be repairable, have high I/O capability with optimal heat removal, have optimized speed, be capable of incorporating an assortment of components of various thicknesses and function, and be hermetically sealed with a high I/O count. Specific processing methods for each of the various module features are described herein, along with additional structural enhancements.
NO-DESCRIPTORS .

33. EXTENDED INTEGRATION SEMICONDUCTOR STRUCTURE AND METHOD OF
MAKING THE SAME, -1990009093/WO-A1/
PCN 1990-08-23 1990009093/WO-A1 NDN- 052-0124-5626-6

INVENTOR- JACOBS, Scott, Laurence
DATE FILED- 1990-01-10
PUBLICATION NUMBER- 1990009093/WO-A1
DOCUMENT TYPE- A1
PUBLICATION DATE- 1990-08-23
INTERNATIONAL PATENT CLASS- H04N00916
PATENT REFERENCE- 4743568/US-A; 4783695/US-A; 4890157/US-A
PCT APPLICATION NUMBER- 09000069/US
PATENT APPLICATION PRIORITY- 301,792
PRIORITY COUNTRY CODE- US
PRIORITY DATE- 1989-01-25
APPLICANT- POLYLITHICS, INC.
PUBLICATION COUNTRY- WO
DESIGNATED COUNTRY- AT; AU; BB; BE; BF; BG; BJ; BR; CA; CF; CG; CH; CM; DE; DK; ES; FI; FR; GA; GB; HU; IT; JP; KP; KR; LK; LU; MC; MG; ML; MR; MW; NL; NO; RO; SD; SE; SN; SU; TD; TG
A low cost, lightweight, fast, dense and reliable extended integration semiconductor

structure is provided by forming a thin film multilayer wiring decal (15) on a support substrate and aligning and attaching one or more integrated chips to the decal. A support ring (33) is attached to the decal surrounding the aligned and attached integrated substrate, and the substrate is removed. Reach-through vias connect the decal wiring to the chips.

NO-DESCRIPTORS .

34. REDUCING STEREOLITHOGRAPHIC PART DISTORTION THROUGH ISOLATION OF STRESS, -1989010255/WO-A1/
PCN 1989-11-02 1989010255/WO-A1 NDN- 052-0120-6199-1

INVENTOR- SMALLEY, Dennis, Rollette

DATE FILED- 1989-04-17

PUBLICATION NUMBER- 1989010255/WO-A1

DOCUMENT TYPE- A1

PUBLICATION DATE- 1989-11-02

INTERNATIONAL PATENT CLASS- B29C06724; *G11C01302; *B32B00110

PATENT REFERENCE- 2775758/US-A; 4575330/US-A; 4752498/US-A; 4801477/US-A

PCT APPLICATION NUMBER- 08901560/US

PATENT APPLICATION PRIORITY- 183,015

PRIORITY COUNTRY CODE- US

PRIORITY DATE- 1988-04-18

APPLICANT- 3D SYSTEMS, INC.

PUBLICATION COUNTRY- WO

DESIGNATED COUNTRY- JP; KR

An improved stereolithography system for generating a three-dimensional object (30) by creating a cross-sectional pattern of the object to be formed at a selected surface (23) of a fluid medium (22) capable of altering its physical state in response to appropriate synergistic stimulation by impinging radiation, particle bombardment or chemical reaction, using information defining the object which is specially processed to reduce curl, stress, birdnesting and other distortions, the successive adjacent laminae (30a, 30b, 30c), representing corresponding successive adjacent cross-sections of the object, being automatically formed and integrated together to provide a step-wise laminar buildup of the desired object, whereby a three-dimensional object is formed and drawn from a substantially planar surface of the fluid medium during the forming process. Reducing stereolithographic distortion through isolation of stress is described.

NO-DESCRIPTORS .

Citations from US PATENT FULLTEXT: US2

35. Method of forming patterned polyimide films
PAT 1995-11-28 05470693 NDN- 064-2592-7787-5

INVENTOR- Sachdev, Krishna G.; Whitaker, Joel R.; Ahmad, Umar M.

PATENT NUMBER- 05470693

PATENT APPLICATION NUMBER- 837505

DATE FILED- 1992-02-18

PATENT DATE- 1995-11-28

NUMBER OF CLAIMS- 23

EXEMPLARY CLAIM- 1

FIGURES- 13

ART OR GROUP UNIT- 157

PATENT CLASS- Invention (utility) patent

PATENT ASSIGNEE- International Business Machines Corporation

ASSIGNEE CITY- Armonk

ASSIGNEE STATE- NY

FIRM- Whitham, Curtis, Whitham & McGinn; Ahsan, Aziz M.

US PATENT CLASS- 4303150000

US CLASSIFICATION REFERENCE- X430317000; X430324000; X430329000;
X430330000

INTERNATIONAL PATENT CLASS- 6G03F00726

PATENT REFERENCE- 4353778; 4411735; 4436583; 4690999; 4702792; 4869777;
5122439; 5153303

PATENT REFERENCED BY- 06159666; 06163957; 06293012; 06303230; 06348301;
06352817; 06479395; 06483193; 05609994; 05667922; 05688719; 05755947;
05805424; 05932799; 06611046; 06677209; 06737723; 06756653; 06770537;
06780721; 06781192; 06838764; 06872671; 06073482; 06890847; 06901217

PATENT ASSIGNEE- INTERNATIONAL BUSINESS MACHINES CORPORATION

ASSIGNEE ADDRESS- A CORP. OF NEW YORK ASSIGNEE CITY- AMRONK

ASSIGNEE STATE- NEW YORK

NEW CLASSIFICATION- 4303150000

CURRENT CLASSIFICATION REFERENCE- X257E21257; X257E21578; X430317000;
X430324000; X430329000; X430330000

A method of producing patterned polyimide films using wet development of polyimide precursors through a photoresist mask is disclosed. Low thermal coefficient of expansion (TCE) polyimide patterns are formed by starting with a polyamic acid precursor, typically, that derived from 3,3 prime ,4,4 prime -biphenyltetracarboxylic acid dianhydride-p-phenylenediamine (BPDA-PDA). Polyimide patterns are generated with complete retention of the intrinsic properties of the polyimide backbone chemistry and formation of metallurgical patterns in low TCE polyimide dielectric.

EXEMPLARY CLAIMS- Claim- 1. A method of producing patterned low thermal coefficient of expansion polyimide films, comprising the steps of: applying a polyamic acid precursor layer onto a substrate wherein said polyamic acid precursor in said layer is capable of imidizing to form a polyimide which has a thermal coefficient of expansion approximately equal to said substrate and is selected from the group consisting of 3,3 prime ,4,4 prime -biphenyltetracarboxylic dianhydride-p-phenylenediamine, 3,3,4,4 prime -biphenyltetracarboxylic dianhydride-benzidine, pyromellitic dianhydride-p-phenylenediamine, pyromellitic dianhydride-benzidine, and 3,3 prime 4,4 prime -benzophenone tetracarboxylic acid dianhydride-p-phenylenediamine; partially baking said polyamic acid precursor layer to a point where a significant amount of casting solvent in said polyamic acid precursor layer has been removed but wherein said polyamic acid precursor layer is still subject to development; applying a positive photoresist on said polyamic acid precursor layer; imagewise exposing said positive photoresist to radiation through a mask; developing said positive photoresist with a first developer which is more active for said positive photoresist than for said polyamic acid precursor layer to yield a structure comprised of a patterned photoresist, a polyamic acid precursor layer and a

substrate, said step of developing is performed under conditions where said polyamic acid precursor layer is not etched with said first developer, said first developer being an aqueous developer; immersing said substrate in a second developer which is more active for said polyamic acid precursor layer than for said positive photoresist, said second developer being an aqueous developer; removing polyamic acid precursor material exposed to said second developer to produce a patterned polyamic acid precursor layer; and curing said patterned polyamic acid precursor layer to yield a patterned polyimide which has a low thermal coefficient of expansion.

NO-DESCRIPTORS .

36. Global planarization process

PAT 1994-02-08 05284804 NDN- 064-2519-6676-4

INVENTOR- Moslehi, Mehrdad M.

PATENT NUMBER- 05284804

PATENT APPLICATION NUMBER- 816458

DATE FILED- 1991-12-31

PATENT DATE- 1994-02-08

NUMBER OF CLAIMS- 19

EXEMPLARY CLAIM- 1

FIGURES- 5

ART OR GROUP UNIT- 114

PATENT CLASS- Invention (utility) patent

PATENT ASSIGNEE- Texas Instruments Incorporated

ASSIGNEE CITY- Dallas

ASSIGNEE STATE- TX

FIRM- Garner, Jacqueline J.; Donaldson, Richard L.; Hiller, William E.

US PATENT CLASS- 437228000

US CLASSIFICATION REFERENCE- X216038000; X437195000; X437238000;
X437240000; X437245000

INTERNATIONAL PATENT CLASS- 5H01L021461

PATENT REFERENCE- 4655874; 4676868; 4708770; 4732658; 4775550; 4810335;
4839311; 4962063; 4983545; 5079188; 5110763

PATENT REFERENCED BY- 05879862; 05885900; 05372974; 05532188; 05837603;
06690044; 06355553

PATENT ASSIGNEE- TEXAS INSTRUMENTS INCORPORATED, A DE CORP. ASSIGNEE

ADDRESS- 13500 NORTH CENTRAL EXPRESSWAY ASSIGNEE CITY- DALLAS

ASSIGNEE STATE- TEXAS

NEW CLASSIFICATION- 4386980000

CURRENT CLASSIFICATION REFERENCE- X216038000; X257E21027; X257E21243;
X257E21304; X438010000; X438699000

A novel global planarization process is disclosed which is fully compatible with semiconductor processing. The process disclosed is called metal melt-solidification planarization (MMSP). A layer of a low melting point/high boiling point metal such as tin or a suitable alloy is deposited on a nonplanar wafer surface via physical-vapor deposition or chemical-vapor deposition or evaporation or plating. The wafer is then heated to above the tin melting point, cooled back to resolidify tin, and etched back to form a globally planar surface.

EXEMPLARY CLAIMS- Claim- 1. A method of planarizing a structure lying on a substrate comprising: depositing a disposable planarization layer which is in solid

form at room temperature; forming a liquid melt from said planarization layer over the substrate so as to form a planar liquid melt surface; solidifying said melt so as to form a planar solid layer; etching back said planar solid layer to a predetermined level on said structure.

NO-DESCRIPTORS .

37. Avoiding spin-on-glass cracking in high aspect ratio cavities
PAT 1992-06-02 05119164 NDN- 064-2446-9512-4

INVENTOR- Sliwa, Jr., John W.; Dixit, Pankaj

PATENT NUMBER- 05119164

PATENT APPLICATION NUMBER- 652306

DATE FILED- 1991-02-05

PATENT DATE- 1992-06-02

NUMBER OF CLAIMS- 3

EXEMPLARY CLAIM- 1

FIGURES- 4

ART OR GROUP UNIT- 253

PATENT CLASS- Invention (utility) patent

PATENT ASSIGNEE- Advanced Micro Devices, Inc.

ASSIGNEE CITY- Sunnyvale

ASSIGNEE STATE- CA

FIRM- Benman & Collins

US PATENT CLASS- 2577760000

US CLASSIFICATION REFERENCE- X357071000

INTERNATIONAL PATENT CLASS- 5H01L02934; H01L02348; H01L02946

PATENT REFERENCED BY- 05250472; 05382547; 05393709; 05516720; 05517062; 05661049; 05665632; 05668398; 05716888; 05773361; 05936295; 06025260; 06031286; 06132814; 06136687; 06576976; 06607991; 06734564; 06228744; 06232647; 06251799; 06307265; 06306753

FOREIGN DOCUMENT REFERENCE- 58-4947; 60-49649; 61-160953

FOREIGN COUNTRY CODE- JPX; JPX; JPX

NEW CLASSIFICATION- 2577760000

CURRENT CLASSIFICATION REFERENCE- X257E21581; X257E23142; X257E23144; X257E23167

Before spin-on-glass (SOG) is applied and soft-cured over metal traces (10) having a height/width aspect ratio (of the spaces) of at least 1, the aluminum metal traces are selectively coated with selective tungsten (16). After SOG (18) is spun on and soft-cured, it is etched back to expose the metal interconnects. A selective tungsten wet etch in H sub 2O sub 2 detaches the SOG from the metal walls, leaving silt-like voids (20). Stress-free SOG hard curing may now proceed. A capping layer (22) of SOG may now be applied, soft-cured, then hard-cured. Alternatively, other dielectric materials may be applied as the capping layer. Further, interfacial lateral sidewall voids (24) may be deliberately left unfilled, by employing a capping layer (24 prime) of vapor-deposited oxide. The unfilled voids have a dielectric constant of 1.0, which is useful in extremely high speed devices. The resulting structure is comparatively stress-free as fabricated and is resistant to later environmentally-induced brittle tensile fracture.

EXEMPLARY CLAIMS- Claim- 1. An integrated circuit containing a plurality of low-resistivity metal interconnect layers in which at least two of said adjacent layers are electrically isolated and separated from each other by a cavity having a height H and

a width W and occupied by a first layer of a dielectric material consisting essentially of spin-on-glass partially detached from adjacent interconnect sidewalls and by a second layer of a dielectric material which covers the top of said interconnects and fills at least a portion of a region between said first layer and said sidewalls, leaving a region of closed space located interfacially on said sidewalls, said region having a dielectric constant approximately equal to 1, thereby permitting use of cavities having an aspect ratio of H/W of at least about 1 between said interconnects.

NO-DESCRIPTORS .

38. Method for coplanar integration of semiconductor ic devices

PAT 1991-02-05 04990462 NDN- 064-2405-8655-8

INVENTOR- Sliwa, Jr., John W.

PATENT NUMBER- 04990462

PATENT APPLICATION NUMBER- 337223

DATE FILED- 1989-04-12

PATENT DATE- 1991-02-05

NUMBER OF CLAIMS- 42

EXEMPLARY CLAIM- 1

FIGURES- 40

ART OR GROUP UNIT- 114

PATENT CLASS- Invention (utility) patent

PATENT ASSIGNEE- Advanced Micro Devices, Inc.

ASSIGNEE CITY- Sunnyvale

ASSIGNEE STATE- CA

FIRM- Collins, David W.

US PATENT CLASS- 4370510000

US CLASSIFICATION REFERENCE- X148DIG028; X257661000; X257730000;
X257776000; X437208000; X437226000

INTERNATIONAL PATENT CLASS- 5H01L021304

PATENT REFERENCE- 3301716; 3870850; 4154998; 4322737; 4542397; 4668333;
4858072

PATENT REFERENCED BY- 05102818; 05189595; 05198385; 05233500; 05283107;
05304460; 05395645; 05473513; 05498575; 05545291; 05565705; 05605863;
05648684; 05691248; 05706176; 05783856; 05808330; 05824186; 05834843;
05904545; 05909052; 05925924; 05968150; 06030885; 06150670; 06251219;
06543087; 06559956; 06611050; 06653157; 06687987; 06761302; 06864570;
06287949; 06300149; 06351022; 06348388; 06369445; 06379998; 06440775;
06455945; 06505665; 06890836

PATENT ASSIGNEE- ADVANCED MICRO DEVICES, INC., 901 THOMPSON ROAD,
SUNNYVALE, CA 94088, A CORP. OF DE

NEW CLASSIFICATION- 4381070000

CURRENT CLASSIFICATION REFERENCE- X029834000; X029836000; X148DIG028;
X257661000; X257730000; X257776000; X257E21705; X257E23141; X257E23170;
X257E25012; X257E29022

A high degree of wafer-scale integration of normally incompatible IC devices is achieved by providing a plurality of segments (10), each segment having thereon one or more circuits, circuit elements, sensors and/or I/O connections (14 prime). Each segment is provided with at least one edge (12) having an abutting portion (12a) capable of abutting against a similar edge of a neighboring segment. The segments are placed on the surface of a flotation liquid (20) and are allowed to be

pulled together so as to mate abutting edges of neighboring segments, thereby forming superchips (10 prime). Microbridges (22) are formed between neighboring segments, such as by solidifying the flotation liquid, and interconnections (26) are formed between neighboring segments. In this manner, coplanar integration of semiconductor ICs is obtained, permitting mixed and normally incompatible circuit functions on one pseudomonolithic device as diverse as silicon and III-V digital circuits, III-V optoelectronic devices, static RAMs, charge coupled devices, III-V lasers, superconducting thin films, ferromagnetic non-volatile memories, high electron mobility transistors, and bubble memories, to name a few, to be integrated in any desired combination. The yieldable scale of integration of a given device technology is also greatly extended. The segments are brought together in a particulate-free fashion with high throughput and exacting reproducibility at low cost.

EXEMPLARY CLAIMS- Claim- 1. A method for coplanar integration of semiconductor IC devices comprising: (a) providing segments having at least one edge having an abutting portion capable of abutting against a similar edge of a neighboring segment, each segment having on a top surface thereof at least one of the items selected from the group consisting of circuits, circuit elements, sensors, and input/output connections; (b) arranging said segments on the surface of a flotation liquid such that the top surfaces of each segment are substantially coplanar; (c) allowing said segments to be pulled together so as to mate abutting edges of neighboring segments to form a superchip; (d) forming solid microbridges between neighboring segments to mechanically secure said superchip; and (e) forming electrical interconnections between neighboring segments so as to interconnect various of said circuits, circuit elements, sensors, and input/output connections.

NO-DESCRIPTORS .

39. Electro-optic signal measurement

PAT 1990-05-22 04928058 NDN- 064-2381-4169-7

INVENTOR- Williamson, Steven

PATENT NUMBER- 04928058

PATENT APPLICATION NUMBER- 355514

DATE FILED- 1989-05-23

PATENT DATE- 1990-05-22

NUMBER OF CLAIMS- 23

EXEMPLARY CLAIM- 1

FIGURES- 4

ART OR GROUP UNIT- 267

PATENT CLASS- Invention (utility) patent

PATENT ASSIGNEE- The University of Rochester

ASSIGNEE CITY- Rochester

ASSIGNEE STATE- NY

FIRM- LuKacher, Martin

US PATENT CLASS- 3240960000

US CLASSIFICATION REFERENCE- X359257000

INTERNATIONAL PATENT CLASS- 5G01R02914

PATENT REFERENCE- 4446426; 4603293; 4618449; 4618819; 4790635; 4836633

PATENT REFERENCED BY- 05041783; 05208531; 05434698; 05550370; 05592101;

05952818; 06111416; 06573700; 06587258; 06677769; 06388454; 06400165;

06414473; 06906506

PATENT ASSIGNEE- UNIVERSITY OF ROCHESTER, THE, A NOT-FOR-PROFIT CORP.

NEW CLASSIFICATION- 3240960000

CURRENT CLASSIFICATION REFERENCE- X359257000

Electro-optic probes which are adapted to be placed in the fringe field from electrical signals propagating on conductors (which may be conductors of an integrated circuit) and which modulate optical pulses passing therethrough, for example by modulating the polarization of the light in accordance with the Pockels effect, utilize thin bodies of electro-optic material, such as a single crystal of GaAs in a manner to reduce physical damage to the probe and to the circuit and to precisely locate the probe in the field of the signal being measured, such as adjacent to the conductor of interest. The electro-optic material that is used may also be implanted with high energy ions of low Z materials (e.g. hydrogen or oxygen) so as to create charge trapping sites and to reduce the photo conductivity of the semiconductive electro-optic material sufficiently that the dielectric relaxation time (where photo current through the material reduces by 1/e) is less than the duration of the optical pulses without eliminating the electro-optic (e.g. Pockels) effect.

EXEMPLARY CLAIMS- Claim- 1. In a system for electro-optically measuring an electrical signal which produces a field with an electro-optic element through which said field passes and through which an optical signal also passes and is modulated by said field, said measurement being in accordance with the modulation of said optical signal, an improved probe which comprises a support having a surface with an edge, a strip of flexural material mounted on said surface and extending beyond said edge as a cantilever, said cantilever having a free end, said electro-optical element being mounted on said element between said edge and said free end and extending beyond said free end to a region where said optical signal intersects said element whereby said element is flexurally supported.

NO-DESCRIPTORS .

Citations from US PATENT FULLTEXT: US3

40. Formation and planarization of silicon-on-insulator structures
PAT 1986-08-05 04604162 NDN- 067-2264-7934-2

INVENTOR- Sobczak, Zbigniew P.

PATENT NUMBER- 04604162

PATENT APPLICATION NUMBER- 812531

DATE FILED- 1985-12-23

PATENT DATE- 1986-08-05

NUMBER OF CLAIMS- 11

EXEMPLARY CLAIM- 1

FIGURES- 8

ART OR GROUP UNIT- 131

PATENT CLASS- Invention (utility) patent

PATENT ASSIGNEE- NCR Corporation

ASSIGNEE CITY- Dayton

ASSIGNEE STATE- OH

FIRM- Cavender, J. T.; Salys, Casimer K.

US PATENT CLASS- 1566571000

US CLASSIFICATION REFERENCE- X156643100; X156649100; X156653100;
X156662100; X427308000; X427337000; X427399000; X427407100; X437062000

INTERNATIONAL PATENT CLASS- H01L021308; H01L021312; H01L021318
PATENT REFERENCE- 4025411; 4307180; 4333965; 4361600; 4374011; 4377438;
4407851; 4485551; 4502913; 4561932; 4571819; 4580331
PATENT REFERENCED BY- 04676868; 04814287; 04842675; 04910165; 04923563;
04983545; 05084419; 05110755; 05116460; 05262002; 05458734; 05466621;
05635411; 05691230; 05721174; 05858547; 05892707; 05907170; 05907783;
05909618; 05914511; 05915192; 05936274; 05963469; 05963789; 05973356;
05976930; 05991225; 06004835; 06025225; 06043527; 06046477; 06066869;
06072209; 06093623; 06104061; 06110798; 06124729; 06134175; 06143636;
06150687; 06153468; 06156604; 06156607; 06165836; 06171972; 06174784;
06190950; 06190960; 06191448; 06191470; 06194262; 06194289; 06208164;
06215145; 06225147; 06238976; 06242775; 06246083; 06251752; 06255171;
06266268; 06300204; 06304483; 06306703; 06309950; 06317357; 06528837;
06538330; 06537871; 06552435; 06559032; 06589851; 06597037; 06610566;
06624021; 06630713; 06680240; 06680864; 06689660; 06747305; 06756622;
06764901; 06777744; 06784076; 06798009; 06812516; 06818937; 06852167;
06858504; 06861311; 06881627; 06884687; 06344399; 06348366; 06350635;
06362043; 06362070; 06373138; 06381168; 06399979; 06403429; 06417040;
06418050; 06423613; 06429065; 06434041; 06449186; 06455391; 06465298;
06465865; 06476434; 06477080; 06479370; 06486703; 06486027; 06492233;
06498065; 06509213; 06504201; 06515510; 06890812; 06894532; 06903367

PATENT ASSIGNEE- HYUNDAI ELECTRONICS AMERICA ASSIGNEE ADDRESS- 3101
NORTH FIRST STREET ASSIGNEE CITY- SAN JOSE ASSIGNEE STATE-
CALIFORNIA

NEW CLASSIFICATION- 4384100000

CURRENT CLASSIFICATION REFERENCE- X257E21245; X257E21564; X427308000;
X427337000; X427399000; X427407100; X438425000; X438699000

A process for fabricating silicon-on-insulator structures on semiconductor wafers and planarizing the topology of the patterns formed from the silicon. In the composite, the process provides for the formation of monocrystalline silicon islands electrically isolated by dielectric in substantially coplanar arrangement with surrounding dielectric. According to one practice of the process, substrate silicon islands are initially formed and capped, and thereafter used as masks to direct the anisotropic etch of the silicon substrate to regions between the islands. During the oxidation which follows, the capped and effectively elevated silicon islands are electrically isolated from the substrate by lateral oxidation through the silicon walls exposed during the preceding etch step. The capped regions, however, remain substantially unaffected during the oxidation. With the electrically isolated silicon island in place, a silicon dioxide layer and a planarizing polymer layer are deposited over the wafer. Processing is concluded with a pair of etching operations, the first removing polymer and silicon dioxide at substantially identical rates, and the second removing silicon dioxide and monocrystalline silicon at substantially identical rates.

EXEMPLARY CLAIMS- Claim- 1. A process for fabricating planarized silicon insulator structures on a semiconductor wafer, comprising the steps of: ; etching a monocrystalline silicon substrate to form islands of silicon having defined perimeters; ; capping the tops and sides of the silicon islands with oxidation masks; ; anisotropically etching deeper into the monocrystalline silicon substrate between the capped island and with no material undercut of the capped islands to increase the relative height of the islands; ; oxidizing the lateral walls of silicon formed by the anisotropic etch until the capped silicon is electrically isolated from the silicon substrate; ; depositing a dielectric layer to a thickness greater than the height of the

islands; ; forming a planarized polymer layer over the dielectric layers; ; simultaneously etching the polymer and dielectric layers to remove polymer and dielectric material at substantially equal rates until the polymer layer is absent; and ; simultaneously etching the dielectric layer and the electrically isolated silicon to remove dielectric material and silicon at substantially equal rates.

NO-DESCRIPTORS .

Citations from US PATENT FULLTEXT: US5

41. Incorporation of dielectric layers in a semiconductor
PAT 1992-05-05 05110712 NDN- 196-2443-9436-3

INVENTOR- Kessler, Daniel D.; Wu, Robert W.; Beatty, Christopher C.; Crook, Mark D.

PATENT NUMBER- 05110712

PATENT APPLICATION NUMBER- 547093

DATE FILED- 1990-04-25

PATENT DATE- 1992-05-05

NUMBER OF CLAIMS- 9

EXEMPLARY CLAIM- 1

FIGURES- 5

ART OR GROUP UNIT- 156

PATENT CLASS- Invention (utility) patent

PATENT ASSIGNEE- Hewlett-Packard Company

ASSIGNEE CITY- Palo Alto

ASSIGNEE STATE- CA

FIRM- Cochran, II, William W.

US PATENT CLASS- 430312000O

US CLASSIFICATION REFERENCE- X216051000; X216058000; X216066000;
X427096000; X427099000; X430313000; X430314000; X430316000; X430317000;
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INTERNATIONAL PATENT CLASS- 5G03C00500

PATENT REFERENCE- 4367119; 4447824; 4495220; 4539222; 4745045

PATENT REFERENCED BY- 05169802; 05244837; 05410185; 05565384; 05593921;
05818110; 05847457; 05912188; 05935766; 06027995; 06052261; 06054384;
06080529; 06117764; 06133141; 06143476

FOREIGN DOCUMENT REFERENCE- EP-A-0-046 525; 158884

FOREIGN COUNTRY CODE- EPX; JPX

A system for integrating a composite dielectric layer in an integrated circuit to facilitate fabrication of a high density multi-level interconnect with external contacts. The composite dielectric layer comprises of a polymer layer which normally comprises a polyimide that is deposited using conventional spin-deposit techniques to form a planarized surface for deposition of an inorganic layer typically comprising silicon dioxide or silicon nitride. The inorganic layer is etched using standard photoresist techniques to form an inorganic mask for etching the polymer layer. A previously deposited inorganic layer functions as an etch stop to allow long over etches to achieve full external contacts which, in turn, allows high density interconnect systems on multiple levels.

EXEMPLARY CLAIMS- Claim- 1. A process for forming a composite dielectric sandwich

in an integrated circuit through the use of inorganic dielectric layers comprising the steps of: (a) forming a first inorganic dielectric layer over at least one underlying layer of said integrated circuit that has sufficient strength to protect said underlying layer by distributing stress from subsequently formed metal features that are deposited on said first inorganic dielectric layer; (b) forming first metal features on said first inorganic dielectric layer; (c) forming a polymer layer over said first inorganic dielectric layer and said first metal features of said integrated circuit, said polymer layer being substantially uniformly distributed to provide a substantially planarized surface; (d) depositing a second inorganic dielectric layer in said integrated circuit over said polymer layer that provides sufficient strength to protect said polymer layer by distributing stress from subsequently formed second metal features that are deposited on said second inorganic dielectric layer; (e) forming a mask on said second inorganic dielectric layer; (f) etching said second inorganic dielectric layer using said mask as a masking pattern to form an inorganic dielectric mask and to provide a protective layer for etching of any subsequently deposited polymer layers; (g) etching said polymer layer using said inorganic dielectric mask as a masking pattern to essentially remove all polymer unmasked by said inorganic dielectric mask between said inorganic dielectric mask and said first inorganic dielectric layer such that said first inorganic dielectric layer functions as a protective layer and etch stop for said underlying layers wherever said etching of said polymer layer continues after all of said unmasked polymer has been removed to fully expose any existing external contact surfaces of said first metal features; (h) maintaining said second inorganic dielectric layer as an insulating layer that, together with said polymer layer, forms said composite dielectric sandwich that has sufficient strength to distribute stress from subsequently formed second metal features and that remains in said integrated circuit as an etch stop layer for subsequently formed layers in a multilayer integrated circuit; (i) forming said second metal features on said second inorganic dielectric layer an in vias formed by etching said polymer layer.

NO-DESCRIPTORS .

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